

Using the UCD3138HSFBEVM-029

User's Guide



Literature Number: SLUUA95
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Digitally Controlled Hard-Switching Full-Bridge DC-DC Converter

1 Introduction

This EVM, UCD3138HSFBEM-029 is to help evaluate the UCD3138RHA 40-pin digital control device in a 48-V telecom power conversion application and then to aid in UCD3138 design. The EVM is a standalone Symmetrical Hard Switching Full-Bridge (HSFB) DC-DC power converter.

The UCD3138HSFBEM-029 can be used as it is delivered without additional work, from either hardware or firmware, to evaluate a hard switching symmetrical full-bridge DC-DC converter. This EVM allows for some of its design parameters to be re-tuned using a GUI based tool, called Texas Instruments Fusion Digital Power Designer. It is also possible to load custom firmware with user's own definition and development.

This user's guide provides basic evaluation instruction from a viewpoint of system operation in a standalone symmetrical HSFB DC-DC power converter.

WARNING

- **High voltages are present on this evaluation module during operation and for a while even after power off. This module should only be tested by skilled personnel in a controlled laboratory environment.**
- **High temperature exceeding 60C may be found during EVM operation and for a while even after power off.**
- **This EVM's purpose is to facilitate the evaluation of digital control in a hard switching full bridge dc converter using the UCD3138, and cannot be tested and treated as a final product.**
- **Read and understand this user's guide thoroughly before starting any physical evaluation.**

2 Description

The UCD3138HSFBEVM-029 demonstrates a symmetrical hard switching full-bridge DC-DC power converter with digital control using the UCD3138RHA 40-pin device. This EVM is with preloaded firmware that provides the required control functions for an HSFB converter. For details of the firmware please contact TI. UCD3138HSFBEVM-029 accepts a DC input from 36 V_{DC} to 72 V_{DC}, and outputs a nominal 12 V_{DC} with full output load power 360 W, or full output current 30 A.

2.1 Typical Applications

- 48-V Telecom DC-DC Power Conversion
- Servers
- Telecommunication Systems

2.2 Features

- Digitally Controlled and Standalone Hard Switching Full-Bridge DC-DC Power Conversion
- Voltage Mode Control
- Secondary Side Control
- DC Input from 36 V_{DC} to 72 V_{DC}
- 12 V_{DC} Regulated Output from No Load to Full Load
- Full-Load Power 360 W, or Full-Load Current 30 A
- High Efficiency
- Constant Soft-tart Time
- Protection: Over Voltage, Under Voltage, Over Current, and Over Temperature
- Constant Current and Constant Power
- Input Voltage Feed Forward Control
- PMBus Communications
- Test Points to Facilitate Device and Topology Evaluation

3 Performance Specifications

Table 1. UCD3138HSFBEVM-029 Specifications

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|---------------------------------------|--|-----|-------|-----|-----------------|
| Input Characteristics | | | | | |
| Voltage operation range | | 36 | | 72 | V _{DC} |
| Input UVLO On | | | 35 | | V _{DC} |
| Input UVLO Off | | | 32 | | V _{DC} |
| Input current | Input = 36 V _{DC} , Full Load = 30A | | | 11 | A |
| Input current | Input = 48 V _{DC} , Full Load = 30A | | | 9 | A |
| Input current | Input = 72 V _{DC} , Full Load = 30A | | | 6 | A |
| Output Characteristics | | | | | |
| Output voltage, V _{OUT} | No Load to Full Load | | 12 | | V _{DC} |
| Output load current, I _{OUT} | 36 to 72 V _{DC} | | | 30 | A |
| Output voltage ripple | 48 V _{DC} and Full Load = 30A | | 30 | | mVpp |
| Systems Characteristics | | | | | |
| Switching frequency | | | 200 | | kHz |
| Peak efficiency | 48 V _{DC} , Load = 20A | | 94.5% | | |
| Full load efficiency | 48 V _{DC} , Full Load = 30A | | 93.5% | | |
| Operating temperature | Typical 400 LFM forced air flow | | 25 | | °C |

4 Schematics

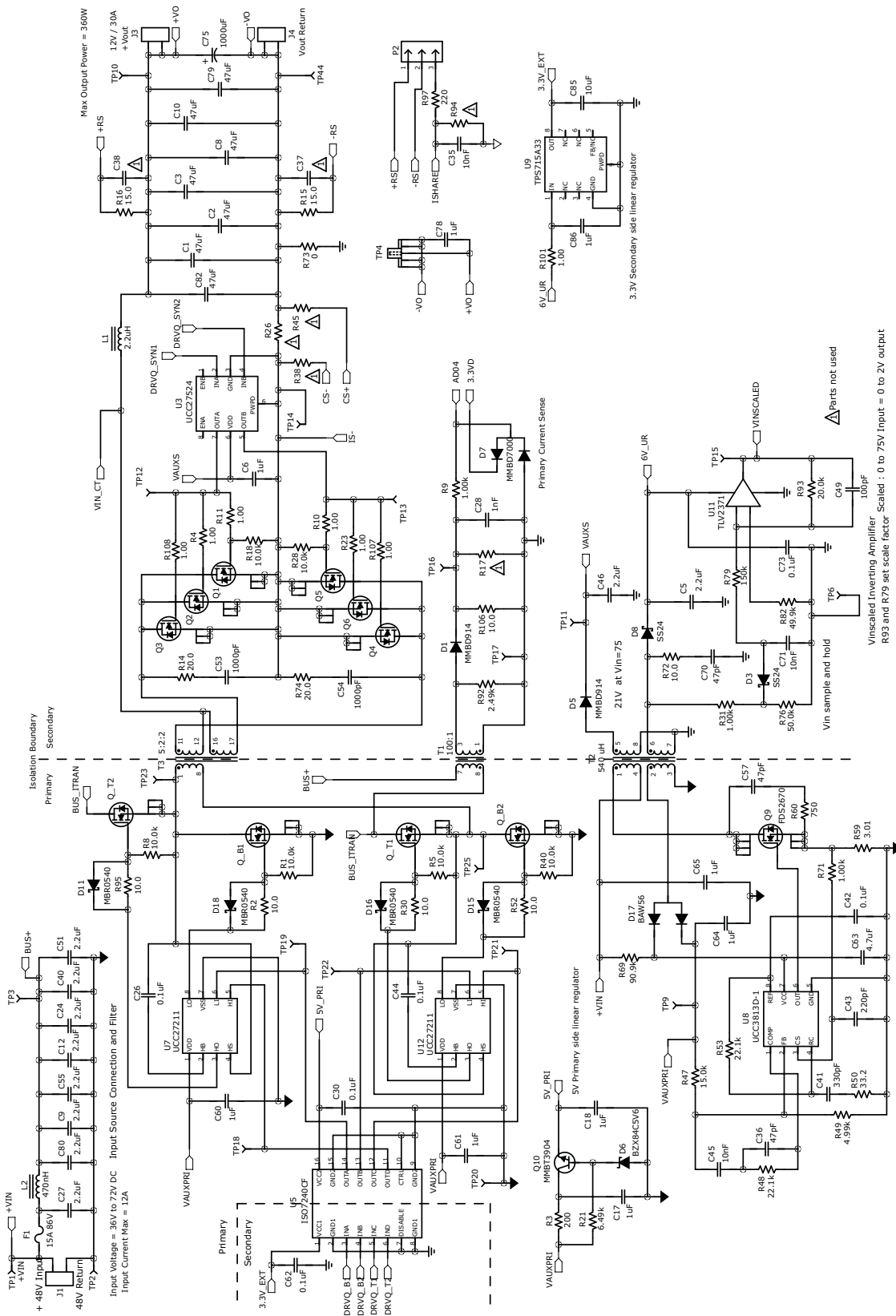


Figure 1. UCD3138HSFBEVM-029 Schematics Sheet 1 of 3

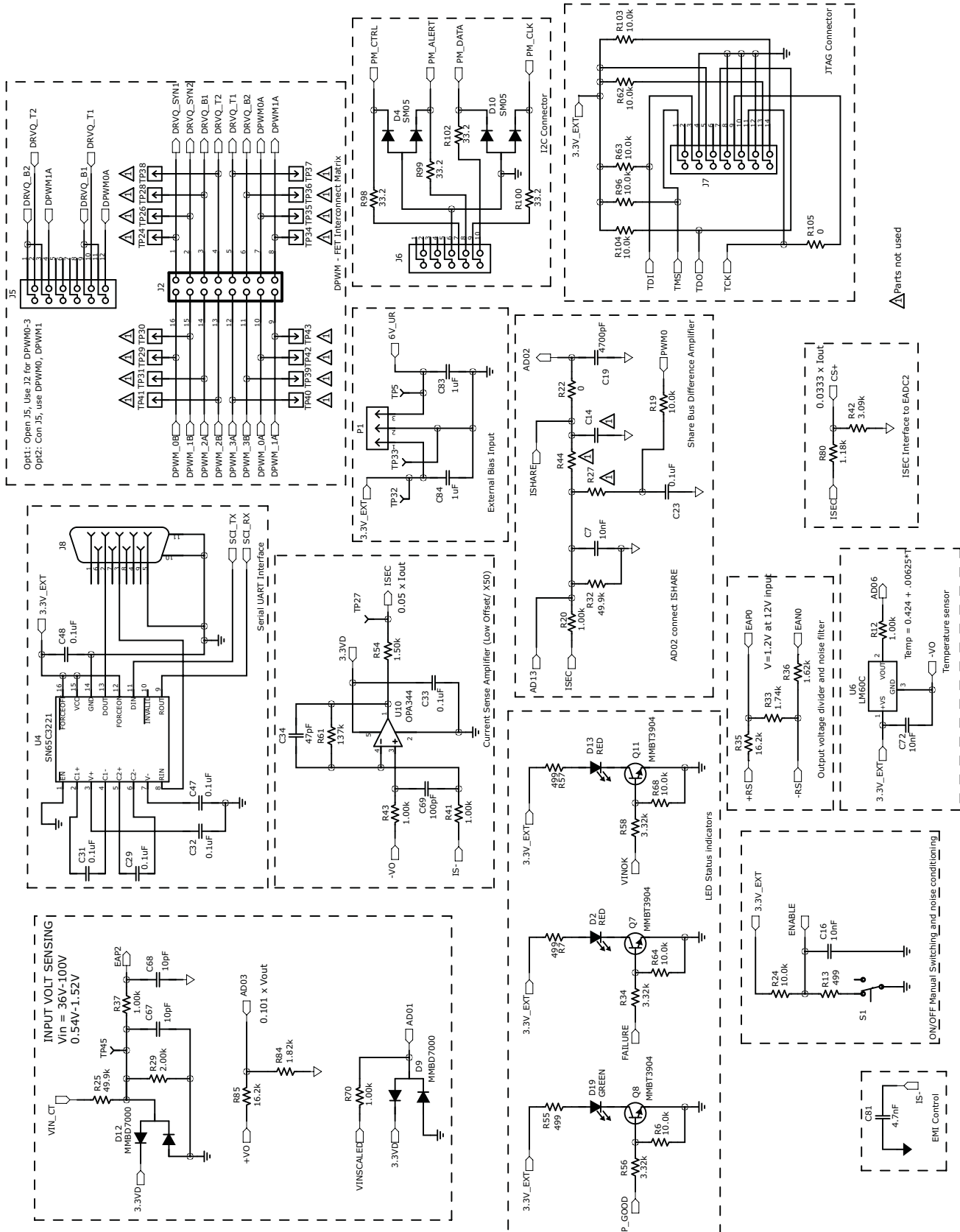


Figure 2. UCD3138HSFBEVM-029 Schematics Sheet 2 of 3

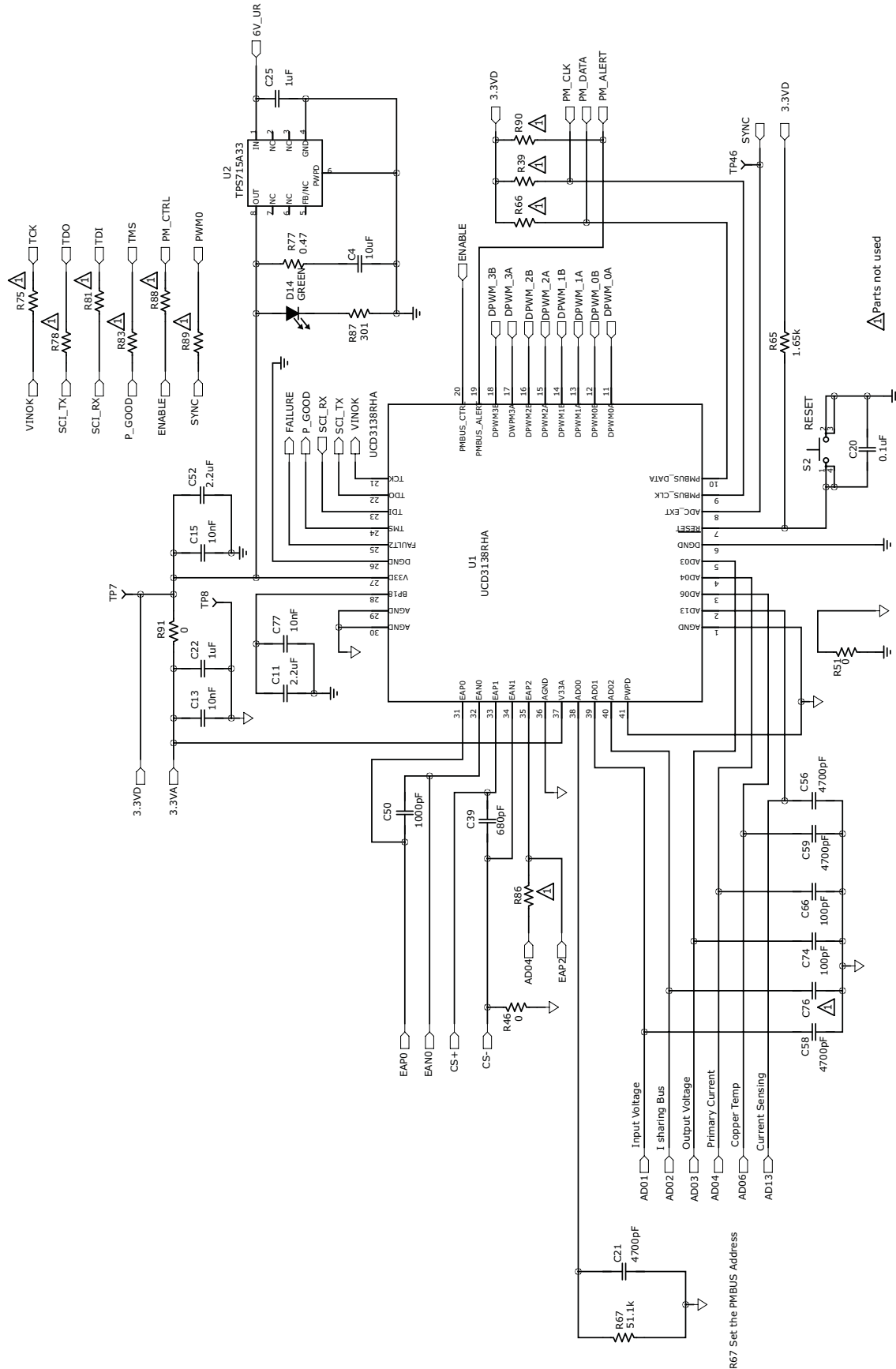


Figure 3. UCD3138HSFBEVM-029 Schematics Sheet 3 of 3

5 Test Setup

5.1 Test Equipment

DC Voltage Source: capable of 36 V_{DC} to 72 V_{DC}, adjustable, with minimum power rating of 400W, or current rating not less than 12A, with current limit function.

DC Multi-meter: 1 unit capable of 0 V_{DC} to 75 V_{DC} input range, four digits display preferred; and 1 unit capable of 0 V_{DC} to 15 V_{DC} input range, four digits display preferred.

Output Load: DC load capable of receiving 0 V_{DC} to 15 V_{DC}, 0 to 30A, and 0 to 360W or greater, with display such as load current and load power.

Current-meter, DC, optional in case the load has no display, 1 unit, capable of 0 to 30A. A low ohmic shunt and DMM are recommended.

Oscilloscope: capable of 500MHz full bandwidth, digital or analog, if digital 5Gs/s or better

Fan: 400 LFM forced air cooling

Recommended Wire Gauge: capable of 30A, or better than #14 AWG, with the total length of wire less than 8 feet (4 feet input and 4 feet return).

5.2 Recommended Test Setup

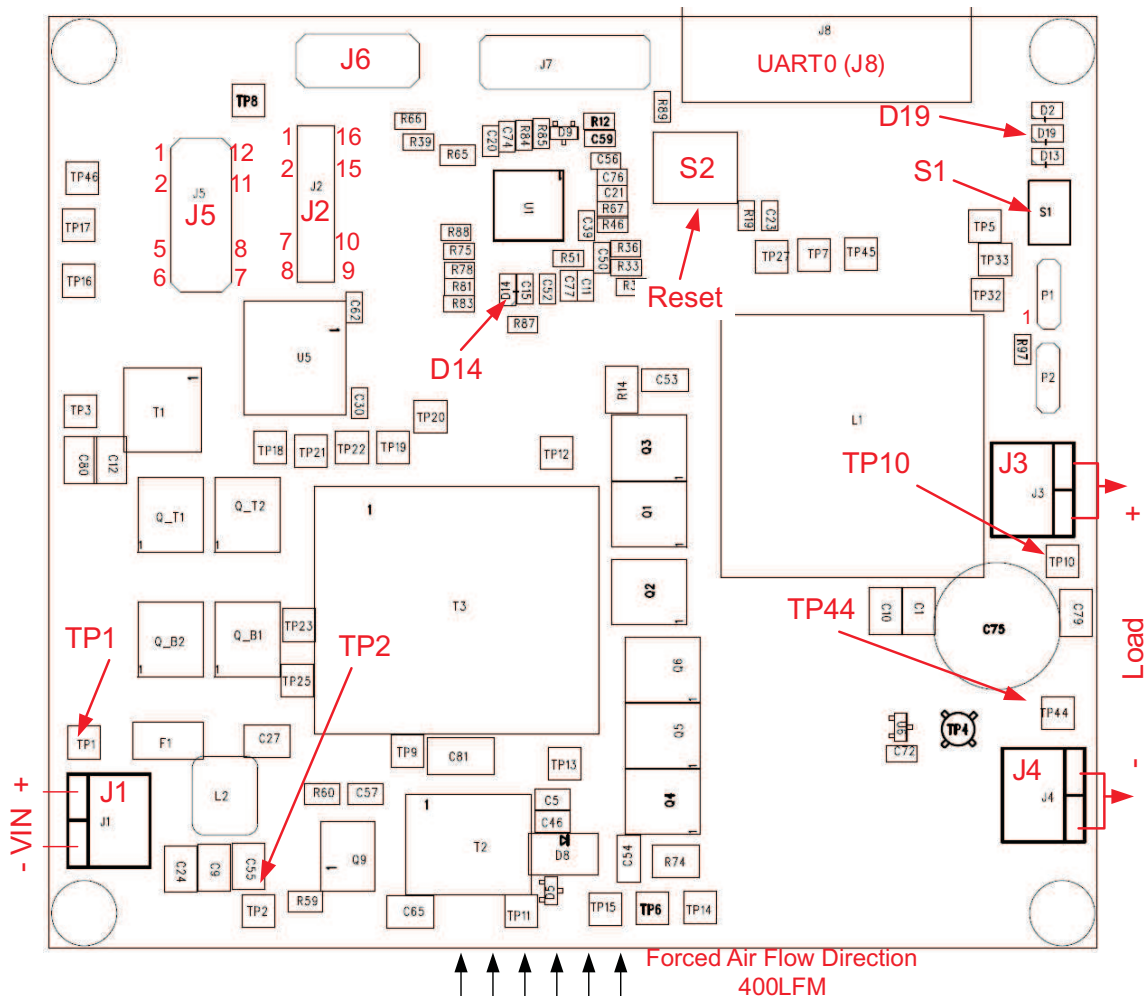


Figure 4. UCD3138FBHSEVM-029 Recommended Test Set Up

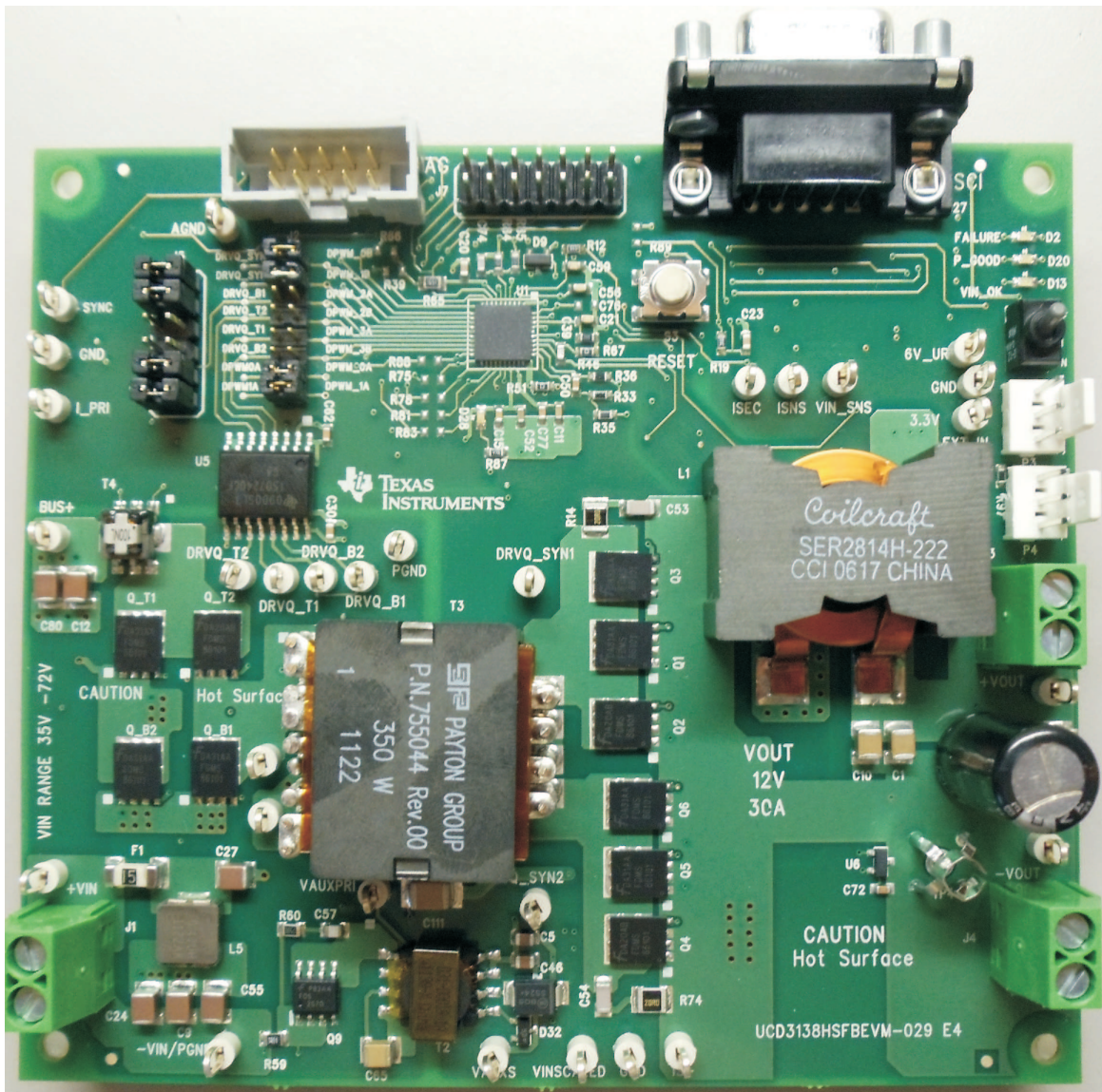


Figure 5. UCD3138HSFBEVM-029 – Board Outlook

6 List of Test Points

Table 2. List of Test Points

| TEST POINTS | NAME | DESCRIPTION |
|-------------|-------------|---|
| TP1 | +VIN | Input Voltage positive |
| TP2 | PWRGND | Input Voltage negative |
| TP3 | +BUS | Input voltage after filter |
| TP4 | Voripple | BNC Vo ripple |
| TP5 | 6V UR Bias | Secondary Bias 6V_UR |
| TP6 | PGND | Secondary bias GND |
| TP7 | 3.3VD | 3.3VD |
| TP8 | AGND | UCD3138 AGND |
| TP9 | VAUXPRI | Primary side bias voltage |
| TP10 | +Vo | +Vout test |
| TP11 | VAUXS | Secondary side bias voltage |
| TP12 | SR_Drive1 | Drive to FET Q1, 2 and Q3 |
| TP13 | SR_Drive2 | Drive to FET Q4, 5 and Q6 |
| TP14 | IS- | Secondary side current sense negative |
| TP15 | VINSCALED | VIN monitoring sense on secondary side |
| TP16 | I_Pri | Primary side current sense transformer output on secondary side |
| TP17 | PGND | Secondary bias GND |
| TP18 | DRV_QT2_iso | Q_T2 |
| TP19 | DRV_QB1_iso | Q_B1 |
| TP20 | PWRGND | Input Voltage negative |
| TP21 | DRV_QT1_iso | Q_T1 |
| TP22 | DRV_QB2_iso | Q_B2 |
| TP23 | T3-1 | Transformer T3 pin 1 |
| TP24 | | Not Used |
| TP25 | SW1 | Switch node of Q_T1 and Q_B2 |
| TP26 | | Not Used |
| TP27 | ISEC | Secondary side current copper sensing after conditioning |
| TP28 | | Not Used |
| TP29 | | Not Used |
| TP30 | | Not Used |
| TP31 | | Not Used |
| TP32 | 3.3VEXT | 3.3V_EXT |
| TP33 | PGND | Secondary bias GND |
| TP34 | | Not Used |
| TP35-43 | | Not Used |
| TP44 | -VO | -Vout test |
| TP45 | EAP2 | EAP2 |
| TP46 | SYNC | UCD3138 SYNC |

7 List of Terminals

Table 3. List of Terminals

| TERMINAL | NAME | DESCRIPTION |
|----------|-----------|--|
| J1 | VIN Input | 2-pin, input voltage, 36 V _{DC} to 72 V _{DC} |
| J2 | Driver-A | 16-pin header, DPWM to driver configuration |

Table 3. List of Terminals (continued)

| TERMINAL | NAME | DESCRIPTION |
|-----------------|-------------|--|
| J3 | +VO | 2-pin, output power positive |
| J4 | -Vo | 2-pin, output power negative |
| J5 | Driver-B | 12-pin header, DPWM to driver configuration |
| J6 | PMBus | 10-pin PMBus connection |
| J7 | JTAG | 14-pin JTAG connection |
| J8 | UART0 | Standard UART connection, RS232, 9-pin female |
| P1 | Bias | External bias terminal for firmware debugging without power stage on |
| P2 | ISHARE | ISHARE and load current sense |

8 Test Procedure

8.1 Efficiency Measurement Procedure

WARNING

Danger of electrical shock. High voltage present during the measurement.

Do not leave EVM powered when unattended.

Danger of heat burn from high temperature.

1. Refer to Figure 4 for basic set up to measure power conversion efficiency. The required equipment for this measurement is listed in Section 5.1.
2. Before making electrical connections, visually check the boards to make sure no shipping damage occurred.
3. In this EVM package, two EVMs are included, UCD3138HSFBEM-029, and USB-TO-GPIO. For this measurement, the UCD3138HSFBEM-029 board is needed.
4. Connect the DC voltage source to J1-1 (+) and J1-2 (-). Set up the DC output voltage in the range specified in Table 1, between $36 V_{DC}$ and $72 V_{DC}$; set up the DC source current limit 12A.
5. Connect an electronic load with either constant current mode or constant resistance mode. The load range is from zero to 30A.
6. Check and make sure the jumpers are installed correctly on J2 and J5.
 - (a) J2 should be jumped across to connect its 1-16, 2-15, 7-10, and 8-9.
 - (b) J5 should be jumped across to connect its 1-12, 2-11, 5-8, and 6-7.

WARNING

Follow the connections correctly to avoid possible damages.

7. It is recommended to use the switch S1 to turn on the board output after the input voltage is applied to the board. Before applying input voltage, make sure the switch, S1, is in the "OFF" position.
8. If the load does not have a current or a power display, a current meter or low ohmic shunt and DMM will be needed between the load and the board for current measurements.
9. Connect a volt-meter across the output connector and set the volt-meter scale 0 to 15V on its voltage, DC.
10. Turn on the DC voltage source output, flip S1 to "ON" and vary the load. Record output voltage and current measurements.

8.2 Equipment Shutdown

1. Shut down the DC voltage source
2. Shut down the electronic load.

9 Performance Data and Typical Characteristic Curves

Figure 6 through Figure 14 present typical performance results for UCD3138HSFBEMV-029.

9.1 Efficiency

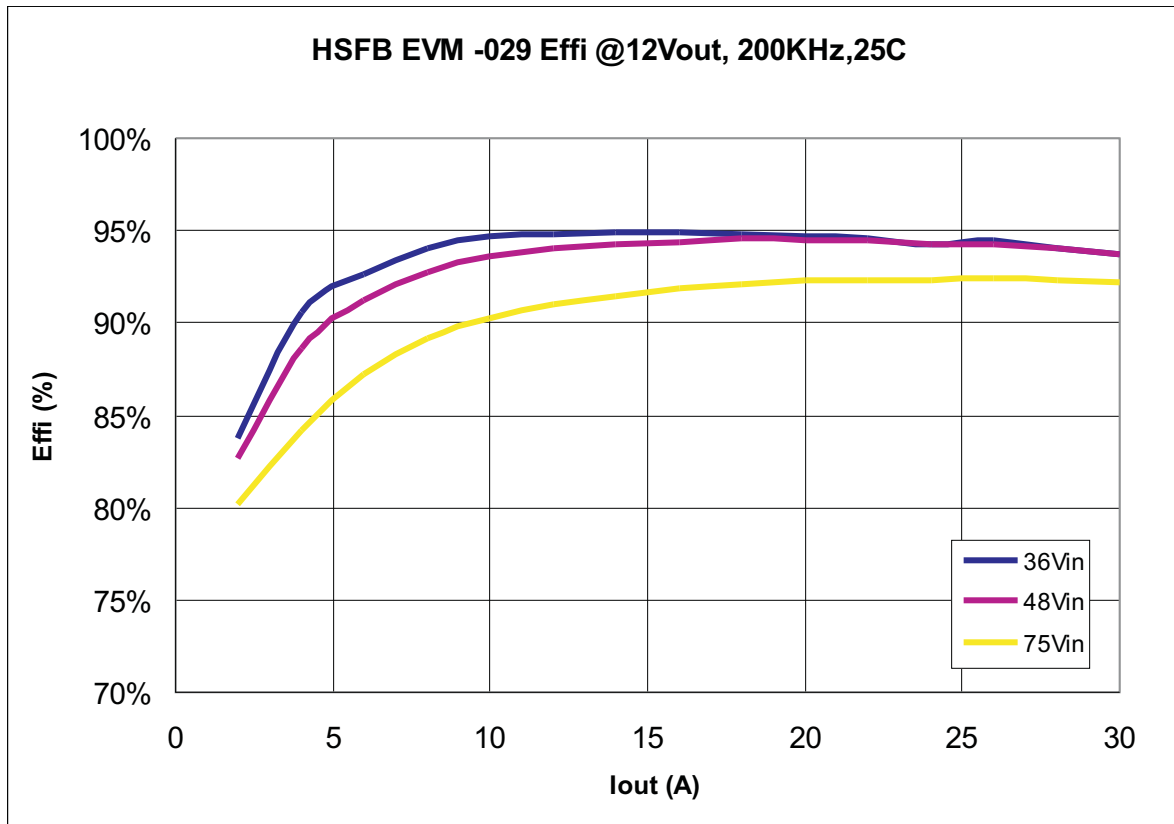


Figure 6. UCD3138HSFBEMV-029 Efficiency

9.2 Load Regulation

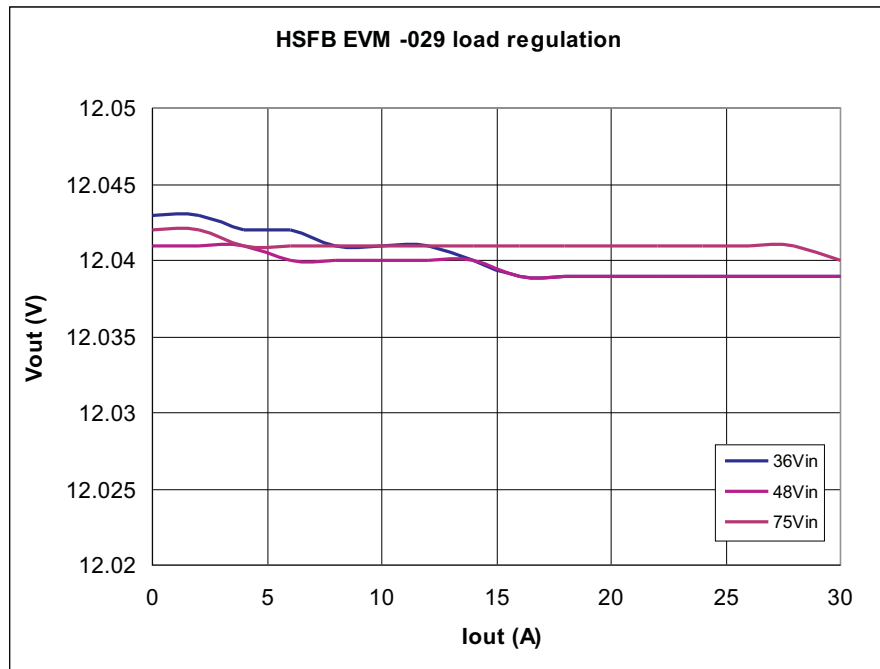


Figure 7. UCD3138HSFBEM-029 Load Regulation

9.3 Line Regulation

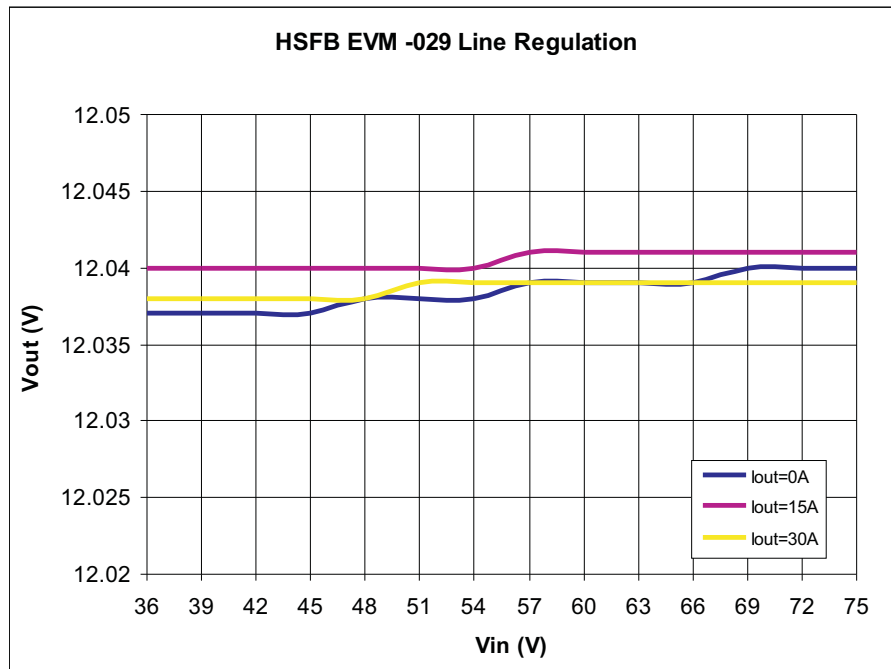


Figure 8. UCD3138HSFBEM-029 Line Regulation

9.4 Constant Power Constant Current (CPCC)

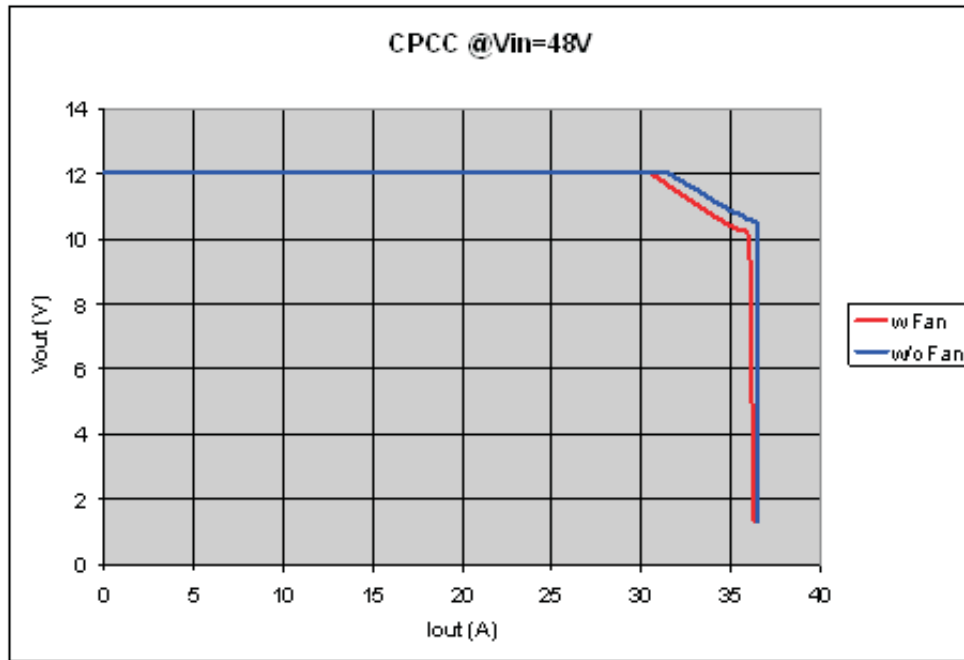


Figure 9. Constant Power Constant Current

9.5 Output Voltage Ripple

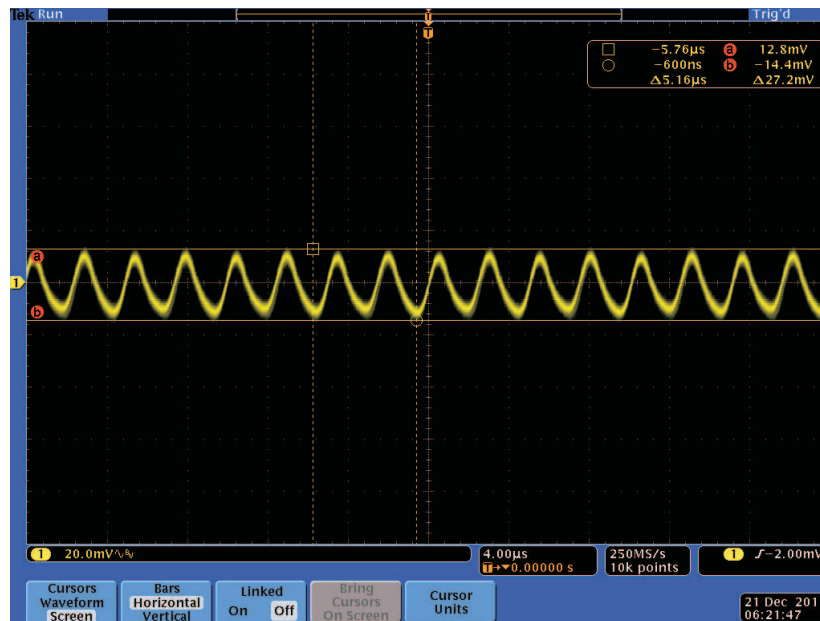


Figure 10. Output Voltage Ripple at 48 V_{DC} and Half Load, 27.2mV

9.6 Output Turn On

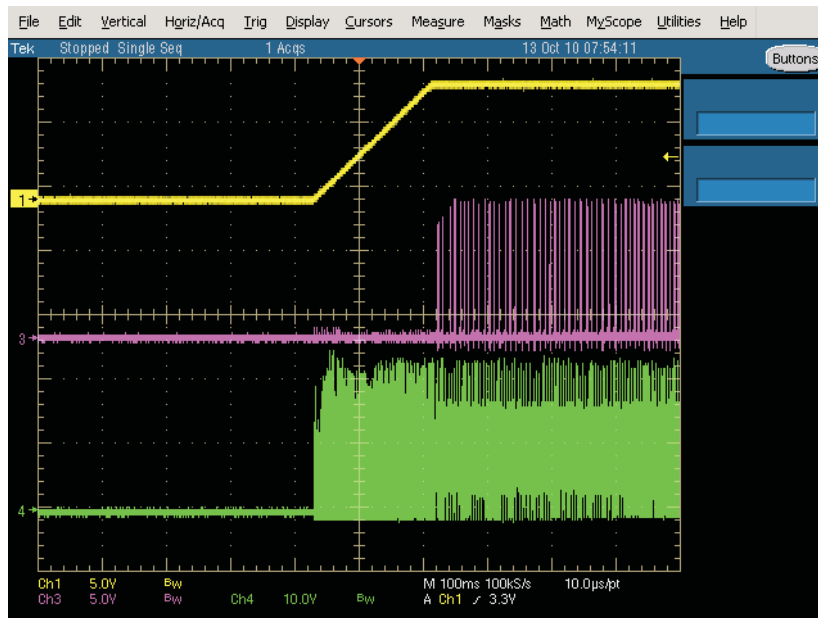


Figure 11. Output Turn On 48 V_{DC} with Load Range (Ch 1 = V_o, Ch 3= DPWM1B, Ch 4 = V_{ct}, load = 1A)

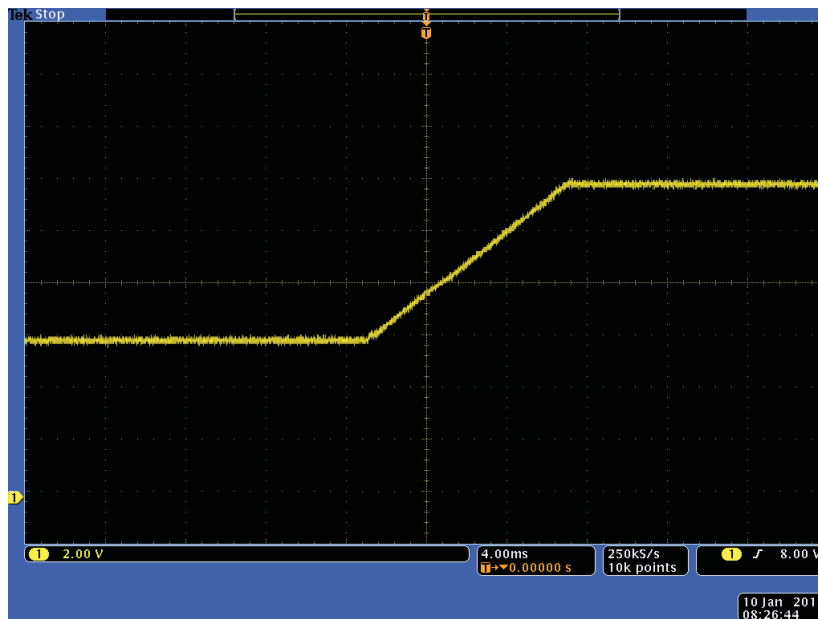


Figure 12. Output Turn On 48 V_{DC} with 6V Prebias

9.7 Bode Plots

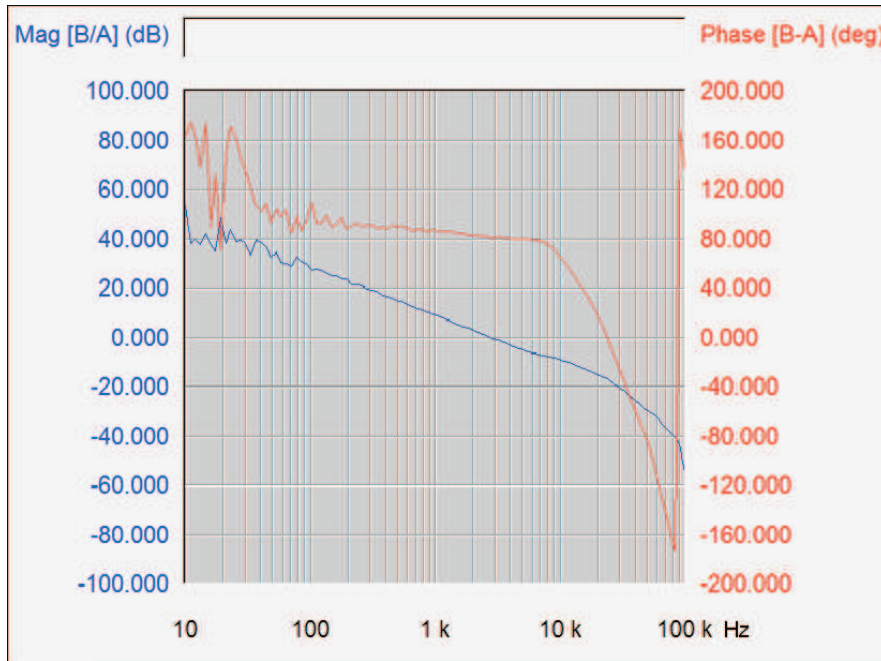


Figure 13. Control Loop Bode Plots at 48 V_{DC} and Half Load

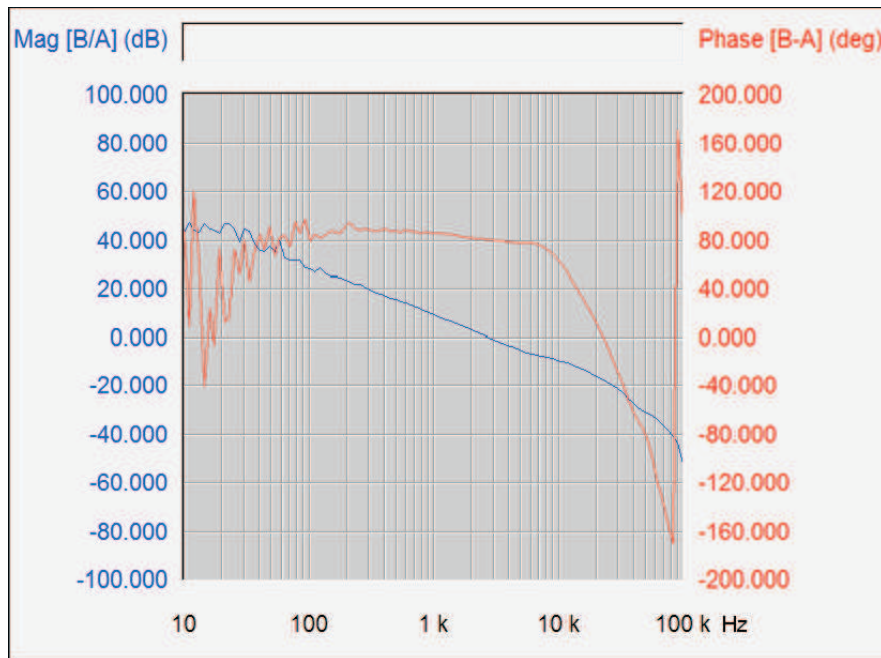


Figure 14. Control Loop Bode Plots at 48 V_{DC} and Full Load

10 EVM Assembly Drawing and PCB Layout

The following figures (Figure 15 through Figure 20) show the design of the UCD3138HSFBEVM-029 printed circuit board. PCB dimensions: L x W = 4.5 x 4.0 in, PCB material: FR4 or compatible, four layers and 2oz copper on each layer



Figure 15. UCD3138HSFBEVM-029 Top Layer Assembly Drawing (top view)

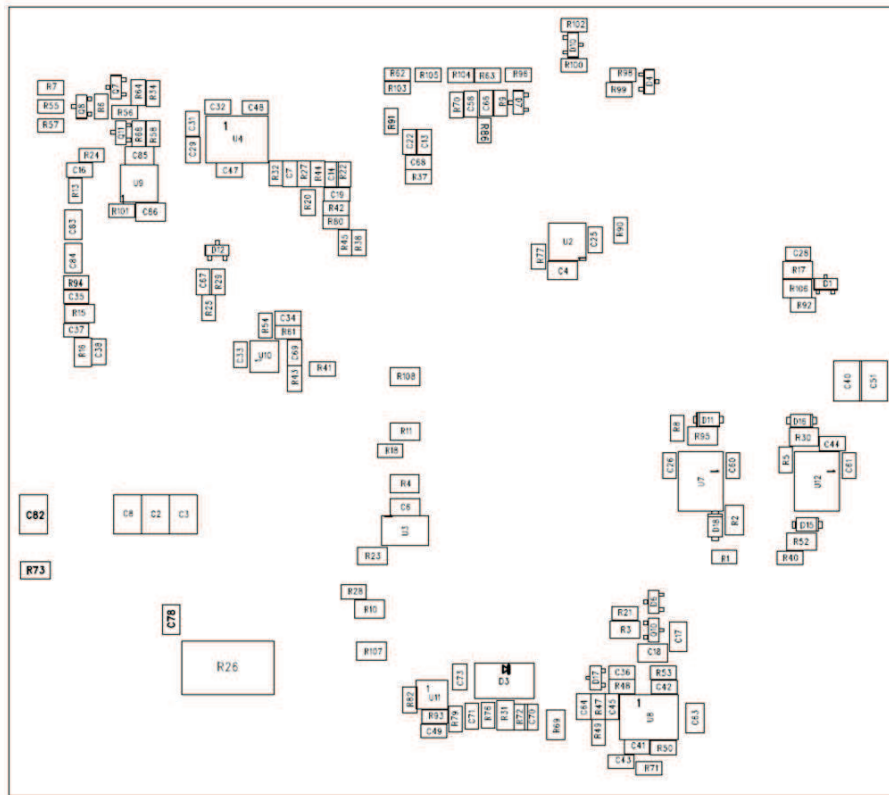


Figure 16. UCD3138HSFBEVM-029 Bottom Assembly Drawing (bottom view)

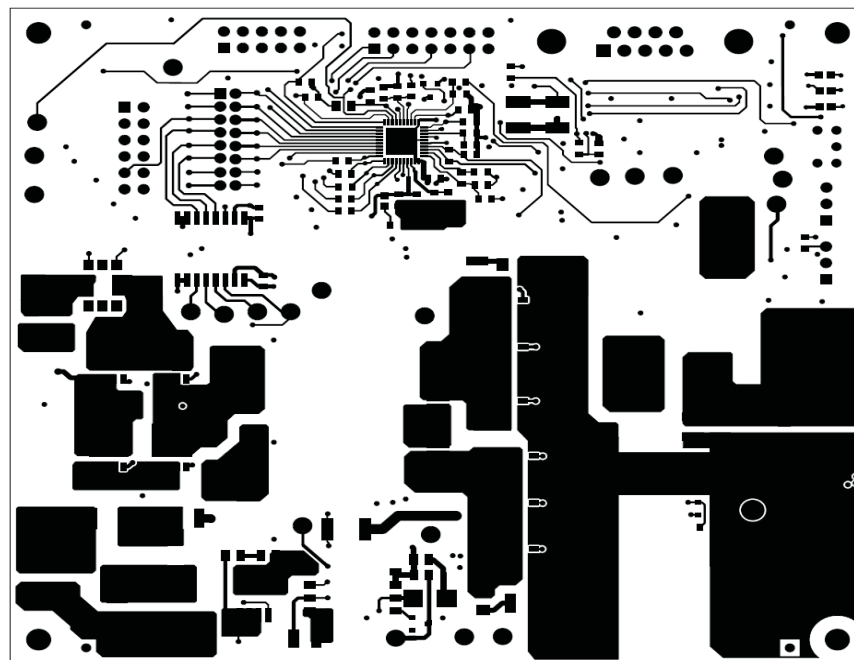


Figure 17. UCD3138HSFBEVM-029 Top Copper (top view)

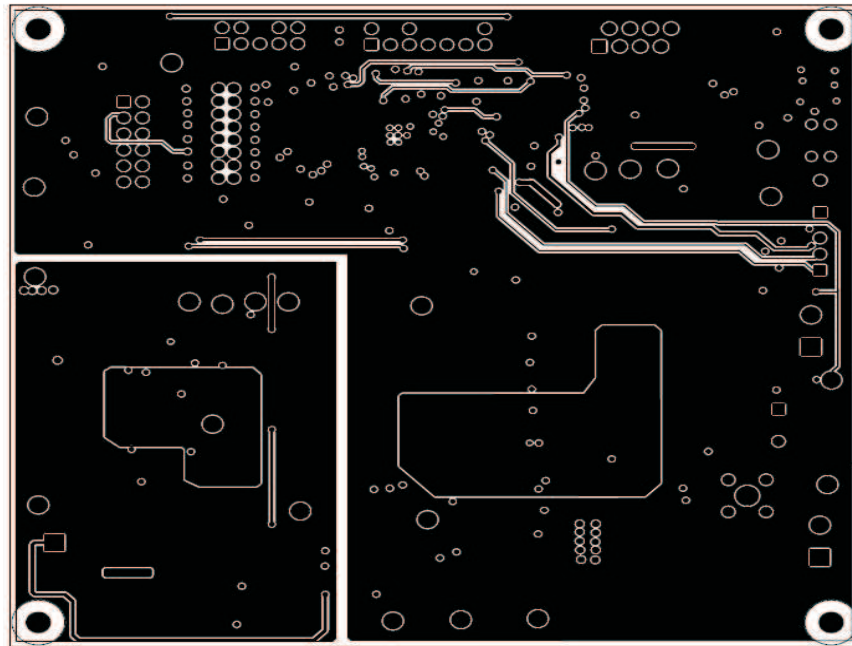


Figure 18. UCD3138HSFBEVM-029 Internal Layer 1 (top view)

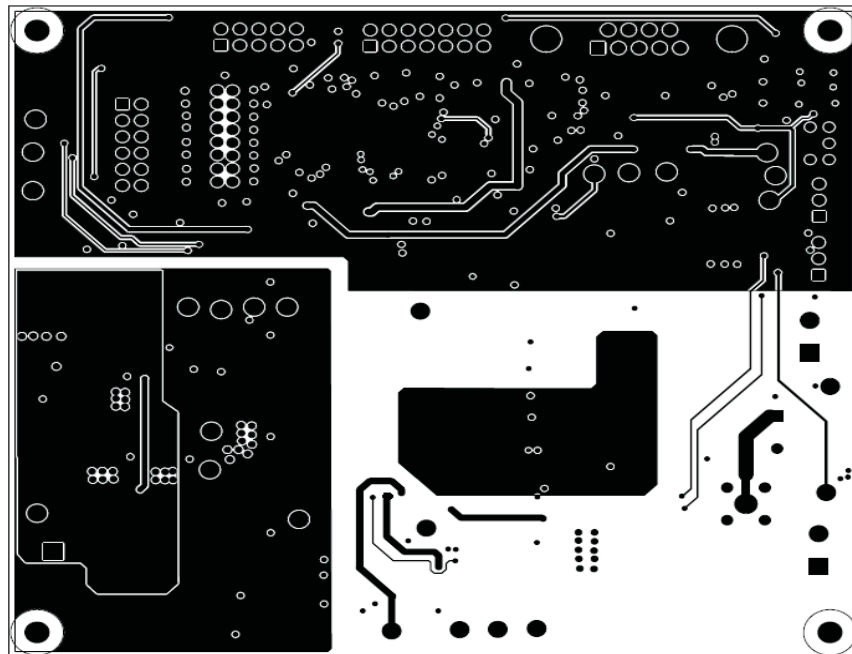


Figure 19. UCD3138HSFBEVM-029 Internal Layer 2 (top view)

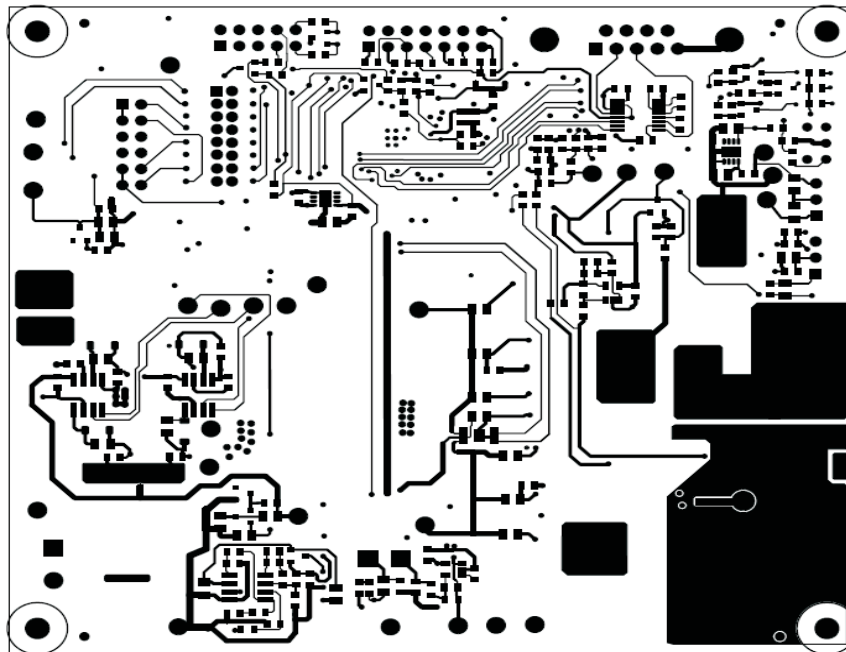


Figure 20. UCD3138HSFBEVM-029 Bottom Copper (top view)

11 List of Materials

Component list based on schematics of [Figure 1](#) though [Figure 3](#).

Table 4. UCD3138HSFBEVM-029 List of Materials

| QTY | RefDes | Description | Part Number | MFR |
|-----|--|--|---------------|---------------|
| 7 | C1, C2, C3, C8, C10, C79, C82 | Capacitor, ceramic, 16V, X5R, 20%, 47uF, 1210 | STD | STD |
| 2 | C11, C52 | Capacitor, ceramic, 6.3V, X7R, 10%, 2.2uF, 0603 | STD | STD |
| 0 | C14, C37, C38, C76 | Capacitor, ceramic, 50V, X7R, 10%, Open, 0603 | STD | STD |
| 5 | C19, C21, C56, C58, C59 | Capacitor, ceramic, 50V, X7R, 10%, 4700pF, 0603 | STD | STD |
| 12 | C20, C23, C26, C29, C30, C31, C32, C33, C42, C44, C47, C48 | Capacitor, ceramic, 50V, X7R, 10%, 0.1uF, 0603 | STD | STD |
| 5 | C22, C25, C60, C61, C64 | Capacitor, ceramic, 16V, X7R, 10%, 1uF, 0603 | STD | STD |
| 1 | C28 | Capacitor, ceramic, 50V, X7R, 10%, 1nF, 0603 | STD | STD |
| 3 | C34, C36, C70 | Capacitor, ceramic, 50V, NP0, 10%, 47pF, 0603 | STD | STD |
| 1 | C39 | Capacitor, ceramic, 50V, X7R, 10%, 680pF, 0603 | STD | STD |
| 2 | C4, C85 | Capacitor, ceramic, 10V, X5R, 10%, 10uF, 0805 | STD | STD |
| 1 | C41 | Capacitor, ceramic, 50V, X7R, 10%, 330pF, 0603 | STD | STD |
| 1 | C43 | Capacitor, ceramic, 50V, X7R, 10%, 220pF, 0603 | STD | STD |
| 4 | C49, C66, C69, C74 | Capacitor, ceramic, 50V, NP0, 10%, 100pF, 0603 | STD | STD |
| 2 | C5, C46 | Capacitor, ceramic, 16V, X7R, 10%, 2.2uF, 0805 | STD | STD |
| 1 | C50 | Capacitor, ceramic, 50V, X7R, 10%, 1000pF, 0603 | STD | STD |
| 2 | C53, C54 | Capacitor, ceramic, 100V, X7R, 10%, 1000pF, 1206 | STD | STD |
| 1 | C57 | Capacitor, ceramic, 200V, NP0, 10%, 47pF, 0805 | STD | STD |
| 7 | C6, C17, C18, C78, C83, C84, C86 | Capacitor, ceramic, 16V, X7R, 10%, 1uF, 0805 | STD | STD |
| 2 | C62, C73 | Capacitor, ceramic, 16V, X7R, 10%, 100nF, 0603 | STD | STD |
| 1 | C63 | Capacitor, ceramic, 16V, X7R, 10%, 4.7uF, 0805 | STD | STD |
| 1 | C65 | Capacitor, ceramic, 100V, X7R, 10%, 1uF, 1210 | STD | STD |
| 2 | C67, C68 | Capacitor, ceramic, 50V, NP0, 10%, 10pF, 0603 | STD | STD |
| 9 | C7, C13, C15, C16, C35, C45, C71, C72, C77 | Capacitor, ceramic, 50V, X7R, 10%, 10nF, 0603 | STD | STD |
| 1 | C75 | Capacitor, Electrolytic, 16V, 20%, 1000uF, 12.5 x 20.00 mm | EEU-EB1C102 | Panasonic |
| 1 | C81 | Capacitor, ceramic, 2000V, X7R, 10%, 4.7nF, 1812 | STD | STD |
| 8 | C9, C12, C24, C27, C40, C51, C55, C80 | Capacitor, ceramic, 100V, X7R, 10%, 2.2uF, 1210 | STD | STD |
| 2 | D1, D5 | Diode, fast switching, 100V, SOT23 | MMBD914LT1G | Fairchild |
| 4 | D11, D15, D16, D18 | Diode, Schottky, 40V, 0.5A, SOD-123 | MBR0540T1G | On Semi |
| 2 | D14, D19 | LED, 565NM, green DIFF, 0603 | SML-LX0603GW | LUMEX |
| 1 | D17 | Diode, small-signal, 85V, 200MA, SOT23 | BAW56-V-GS08 | Vishay-Liteon |
| 2 | D2, D13 | LED, 660NM, super red diff, 0603 | SML-LX0603SRW | Lite On |
| 2 | D3, D8 | Diode, Schottky, 2A, 40V, SMB | SS24T3G | ON SEMI |
| 2 | D4, D10 | Diode, TVS Zener dual, 300W, 5V, SOT23 | SM05T1G | ON SEMI |
| 1 | D6 | Diode, Zener, 225MW, 5.6V, SOT-23 | BZX84C5V6-T1G | ON SEMI |
| 3 | D7, D9, D12 | Diode, dual switch, 100V, SOT23 | MMBD7000LT1G | ON SEMI |
| 1 | F1 | FUSE 15A 86 V _{DC} fast 6125FA, 15A 86V, 2410 | TR2/6125FA15A | Cooper |

Table 4. UCD3138HSFBEM-029 List of Materials (continued)

| | | | | |
|----|--|---|-------------------|-----------|
| 3 | J1, J3, J4 | 2 position 5mm terminal block, TB 2X5mm, 0.40 x 0.35 inch | ED350/2 | OST |
| 1 | J2 | Header 16 position 2mm, header 2mm 16 pos | PRPN062PAEN-RC | Sullins |
| 1 | J5 | Header 12 position 100mil, header 0.1 12 POS", 0.100 inch x 2X6 | PEC06DAAN | Sullins |
| 1 | J6 | Shrouded header 10 pos straight, header 100-2x5 shroudedheader 100-2x5 shrouded0.100 inch x 5 x 2 | N2510-6002-RB | Sullins |
| 0 | J7 | Conn hdr dual 14pos .100 SRT AU, open, 0.100 inch x 2x7 | PEC07DAAN | Sullins |
| 1 | J8 | Connector, 9-pin D, right angle, female, 1.213 x 0.510 | 182-009-213R171 | Norcomp |
| 1 | L1 | Inductor, power, 35A, 2.2uH, 1.100 x 1.100 inch | SER2814H-222KL | Coilcraft |
| 1 | L2 | Inductor, power, 16A, 470nH, 0.255 x 0.270 inch | IHL2525CZERR47M01 | Vishay |
| 2 | P1, P2 | Conn header 3pos .100 vert tin, 3 pin polarized header, 0.100 inch x 3 | 22-27-2031 | Molex |
| 4 | Q_B1, Q_B2, Q_T1, Q_T2 | MOSFET, N-channel, 100V, 60A, 8mohm, QFN | FDMS86101 | Fairchild |
| 6 | Q1, Q2, Q3, Q4, Q5, Q6 | MOSFET, N-channel, 100V, 60A, 8mohm, QFN | FDMS86101 | Fairchild |
| 4 | Q7, Q8, Q10, Q11 | Transistor, NPN, 350mW, 200mA, 40V, SOT23 | MMBT3904 | FAIRCHILD |
| 1 | Q9 | MOSFET, N-channel, 200V, 3A, S08 | FDS2670 | Fairchild |
| 16 | R1, R5, R6, R8, R18, R19, R24, R28, R40, R62, R63, R64, R68, R96, R103, R104 | Resistor, chip, 1/10W, 1%, 10.0k, 0603 | STD | STD |
| 1 | R101 | Resistor, chip, 1/10W, 1%, 1, 0603 | STD | STD |
| 2 | R14, R74 | Resistor, chip, 1/3W, 1%, 20, 1210 | STD | STD |
| 2 | R15, R16 | Resistor, chip, 1/8W, 1%, 15, 0805 | STD | STD |
| 0 | R17 | Resistor, chip, 1/8W, 1%, Open, 0805 | STD | STD |
| 5 | R2, R30, R52, R95, R106 | Resistor, chip, 1/8W, 1%, 10, 0805 | STD | STD |
| 1 | R21 | Resistor, chip, 1/10W, 1%, 6.49k, 0603 | STD | STD |
| 5 | R22, R46, R51, R91, R105 | Resistor, chip, 1/10W, 0, 0603 | STD | STD |
| 4 | R25, R32, R76, R82 | Resistor, chip, 1/10W, 1%, 49.9k, 0603 | STD | STD |
| 0 | R26 | Resistor, current sense , 3W, 1%, open, 0.394 x 0.205 inch | BVS-M-R001-1.0 | Isotek |
| 0 | R27, R38, R39, R44, R45, R66, R75, R78, R81, R83, R86, R88, R89, R90, R94 | Resistor, chip, 1/10W, 1%, open, 0603 | STD | STD |
| 1 | R29 | Resistor, chip, 1/10W, 1%, 2.00k, 0603 | STD | STD |
| 1 | R3 | Resistor, chip, 1/8W, 1%, 200, 0805 | STD | STD |
| 1 | R31 | Resistor, chip, 1/8W, 1%, 1.00k, 0805 | STD | STD |
| 1 | R33 | Resistor, chip, 1/10W, 1%, 1.74k, 0603 | STD | STD |
| 3 | R34, R56, R58 | Resistor, chip, 1/10W, 1%, 3.32k, 0603 | STD | STD |
| 2 | R35, R85 | Resistor, chip, 1/10W, 1%, 16.2k, 0603 | STD | STD |
| 1 | R36 | Resistor, chip, 1/10W, 1%, 1.62k, 0603 | STD | STD |
| 6 | R4, R10, R11, R23, R107, R108 | Resistor, chip, 1/8W, 1%, 1, 0805 | STD | STD |
| 1 | R42 | Resistor, chip, 1/10W, 1%, 3.09k, 0603 | STD | STD |
| 1 | R47 | Resistor, chip, 1/10W, 1%, 15.0k, 0603 | STD | STD |
| 2 | R48, R53 | Resistor, chip, 1/10W, 1%, 22.1k, 0603 | STD | STD |

Table 4. UCD3138HSFBEM-029 List of Materials (continued)

| | | | | |
|----|--|--|---------------|-----------|
| 1 | R49 | Resistor, chip, 1/10W, 1%, 4.99k, 0603 | STD | STD |
| 5 | R50, R98, R99, R100, R102 | Resistor, chip, 1/10W, 1%, 33.2, 0603 | STD | STD |
| 1 | R54 | Resistor, chip, 1/10W, 1%, 1.50k, 0603 | STD | STD |
| 1 | R59 | Resistor, chip, 1/8W, 1%, 3.01, 0805 | STD | STD |
| 1 | R60 | Resistor, chip, 1/8W, 1%, 750, 0805 | STD | STD |
| 1 | R61 | Resistor, chip, 1/10W, 1%, 137k, 0603 | STD | STD |
| 1 | R65 | Resistor, chip, 1/8W, 1%, 1.65k, 0805 | STD | STD |
| 1 | R67 | Resistor, chip, 1/10W, 1%, 51.1k, 0603 | STD | STD |
| 1 | R69 | Resistor, chip, 1/8W, 1%, 90.9k, 0805 | STD | STD |
| 4 | R7, R13, R55, R57 | Resistor, chip, 1/10W, 1%, 499, 0603 | STD | STD |
| 1 | R72 | Resistor, chip, 1/10W, 1%, 10, 0603 | STD | STD |
| 1 | R73 | Resistor, chip, 1/8W, 0, 0805 | STD | STD |
| 1 | R77 | Resistor, chip, 1/10W, 1%, 0.47, 0603 | STD | STD |
| 1 | R79 | Resistor, chip, 1/10W, 1%, 150k, 0603 | STD | STD |
| 1 | R80 | Resistor, chip, 1/10W, 1%, 1.18k, 0603 | STD | STD |
| 1 | R84 | Resistor, chip, 1/10W, 1%, 1.82k, 0603 | STD | STD |
| 1 | R87 | Resistor, Chip, 1/10W, 1%, 301, 0603 | STD | STD |
| 8 | R9, R12, R20, R37, R41, R43, R70, R71 | Resistor, chip, 1/10W, 1%, 1.00k, 0603 | STD | STD |
| 1 | R92 | Resistor, chip, 1/10W, 1%, 2.49k, 0603 | STD | STD |
| 1 | R93 | Resistor, chip, 1/10W, 1%, 20.0k, 0603 | STD | STD |
| 1 | R97 | Resistor, chip, 1/10W, 1%, 220, 0603 | STD | STD |
| 1 | S1 | Switch, on-on mini toggle, SPDT 28V 0.4A, 0.28 x 0.18 inch | G12AP | NKK |
| 1 | S2 | Switch, SPST, PB momentary, sealed washable, 0.245 X 0.251 | KT11P2JM34LFS | C & K |
| 1 | T1 | SMT 100:1 current sense XFMR, 100:01:00, 0.284 x 0.330 inch | PA1005.100 | Pulse |
| 1 | T2 | Transformer, aux. flyback $\pm 10\%$, 540 μ H, 0.400 x 0.480 inch | 031-00019 | XFMR Inc |
| 1 | T3 | Power XFMR 400W 5:2:2, 26x29.5 mm | 755044 | Payton |
| 29 | TP1, TP2, TP3, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20, TP21, TP22, TP23, TP25, TP27, TP32, TP33, TP44, TP45, TP46 | Test point, white, thru hole, 5012, 0.125 x 0.125 inch | 5012 | Keystone |
| 1 | TP4 | Adaptor, 3.5-mm probe clip (or 131-5031-00), 0.200 inch | 131-4244-00 | Tektronix |
| 1 | U1 | UCD3138RHA, Digital Power Controllers, QFN | UCD3138RHA | TI |
| 1 | U10 | OPA344, MIC OP AMP RRIO, SOT23-5 | OPA344NA/250 | TI |
| 1 | U11 | TLV2371, OP AMP 3MHZ RRIO, SOT23-5 | TLV2371IDBVR | TI |
| 2 | U2, U9 | TPS715A33, LDO REG, QFN-8 | TPS715A33DRBT | TI |
| 1 | U3 | UCC27524, Dual HS MOSFET Driver, 5A, HTSSOP | UCC27524DGN | TI |
| 1 | U4 | SN65C3221, LINE DRVR/RCVR 1CH, TSSOP-16 | SN65C3221PWR | TI |
| 1 | U5 | QISO7240CF, UAD CHANNEL 25 MBPS DIGITAL ISOLATOR, SO-16 | ISO7240CFDWR | TI |
| 1 | U6 | LM60C, Temp Sensor, SOT-23 | LM60CIM3X | TI |
| 2 | U7, U12 | UCC27211, HIGH/LOW SIDE DRIVER, 4A, SO8 | UCC27211D | TI |

Table 4. UCD3138HSFBEVM-029 List of Materials (continued)

| | | | | |
|---|----|---------------------------------------|------------|----|
| 1 | U8 | UCC3813D-1, LOW-PWR CUR-MODE PWM, SO8 | UCC3813D-1 | TI |
|---|----|---------------------------------------|------------|----|

Appendix A 12 Digital Full-Bridge Converter Description

A.1 Converter Block Diagram

Figure 21 shows the converter block diagram used in the EVM. The signals used for control and for detection are also defined in Figure 21 in connection to the UCD3138 pins which are listed in Section 12.2 and Figure 22 as well.

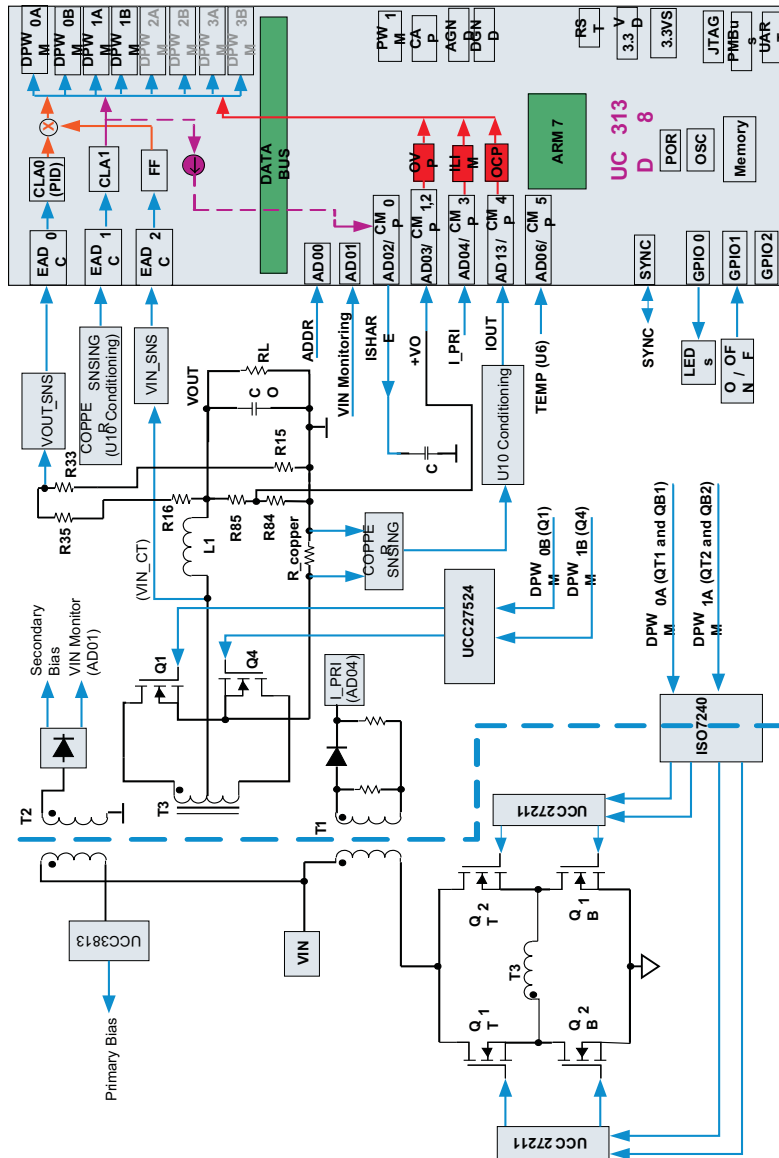


Figure 21. Converter Block Diagram and Pin Definitions

A.2 UCD3138 Pin Definition

The definition of each UCD3138 pin is defined as shown in Figure 21. The definitions shown in Figure 22 are for these pins used in the EVM to make full-bridge converter control. It can be found in Figure 21 how the signals on these pins are used in the converter in this EVM.

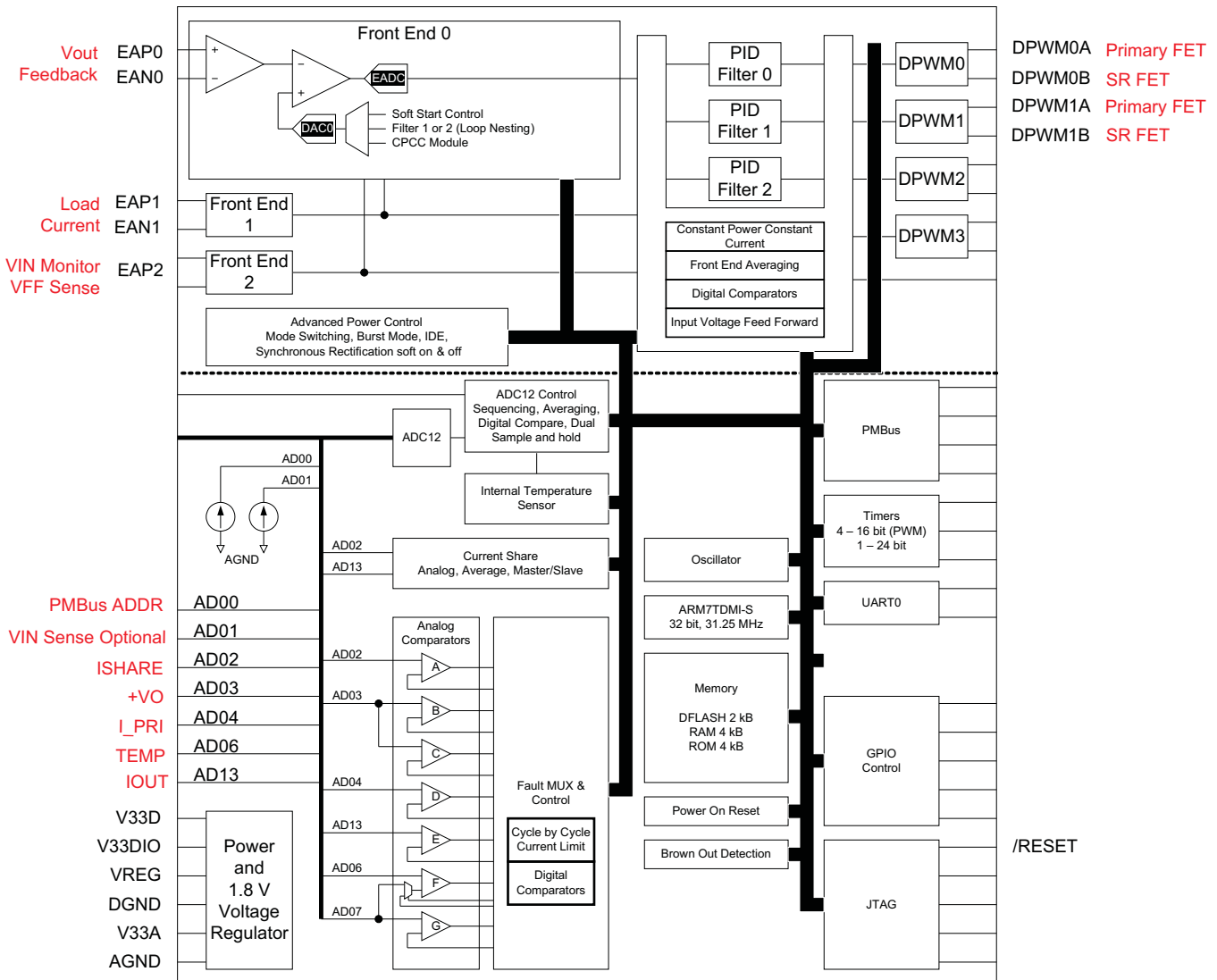


Figure 22. UCD3138 Pin Definition in Hard Switching Full-Bridge Control

A.3 12.3 EVM Hardware – Introduction

In this section, the EVM hardware functions are described.

A.3.1 Power Stage

This EVM implements a traditional symmetrical hard switching full-bridge dc-dc converter topology. The power stage circuit is shown in Figure 23. The complete schematics are shown in Figure 1 through 3. The main power components on the primary side, Q_T1, Q_T2, Q_B1, and Q_B2 form the MOSFET full-bridge converter. These four FETs are controlled by the UCD3138 DPWM module 0 (DPWM0A) and module 1 (DPWM1A). The controller, UCD3138, is located on the secondary side. The driver signals to these four FETs are through digital isolator U5 to transmit from the secondary side to the primary side. The synchronous rectifiers are shown on the same page and are labeled as Q1 to Q3 and Q4 to Q6. They are controlled by DPWM module 0 (DPWM0B) and DPWM module 1 (DPWM1B). Please refer to Figure 22 for DPWM module 0 and 1. The main power transformer is T3. T1 is the current transformer used to sense the primary side current and feed into the secondary side UCD3138 controller through AD04.

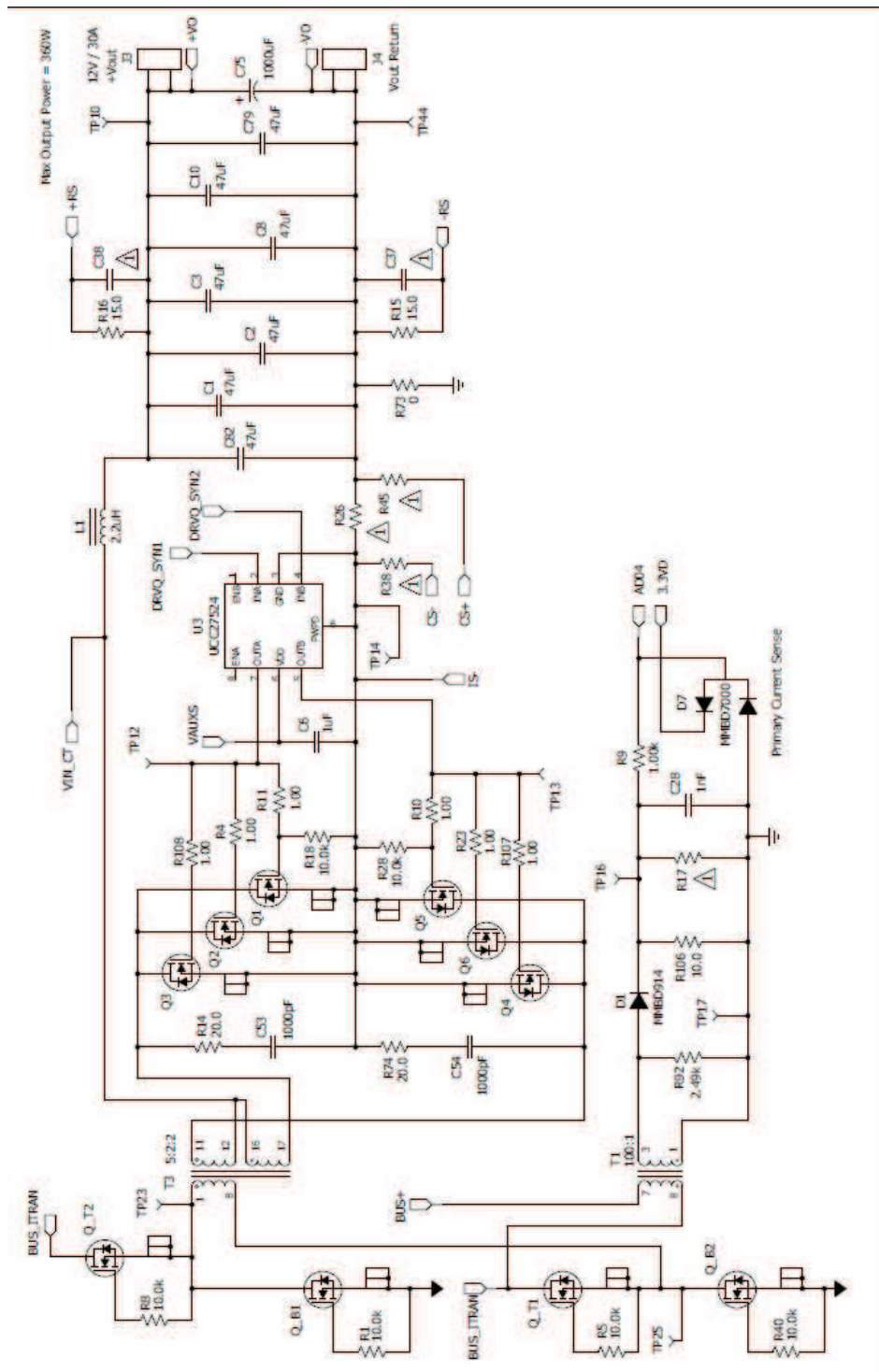


Figure 23. Full-Bridge Converter Power Stage

A.3.2 Bias Power Supply

The main bias supply is a flyback converter using the UCC3813 controller from Texas Instruments. The bias circuit is shown in Figure 24.

In this circuit, one output (VAUXPRI) is on the primary side and two outputs (VAUXS and 6V_UR) are on the secondary side. The feedback signal is taken from VAUXPRI. The secondary side controller needs +3.3V, which is derived from 6V_UR by a regulator (U2) to supply UCD3138 and by a regulator (U9) to supply digital isolator (U5), external temperature sensor (U6) and UART controller (U4). On the primary side a 5V-LDO is to supply the digital isolator to transmit drive signals from the secondary side to the primary side. The three LDO associated bias circuits are shown in Figure 25.

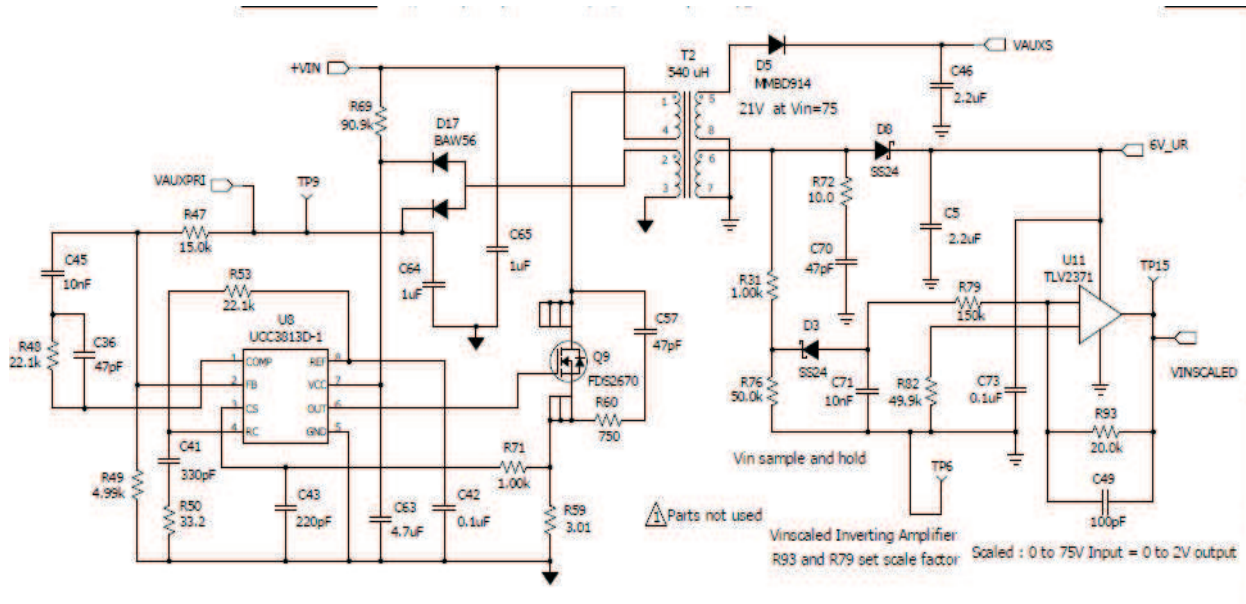


Figure 24. Main Bias Circuit and Input Voltage Optional Monitoring

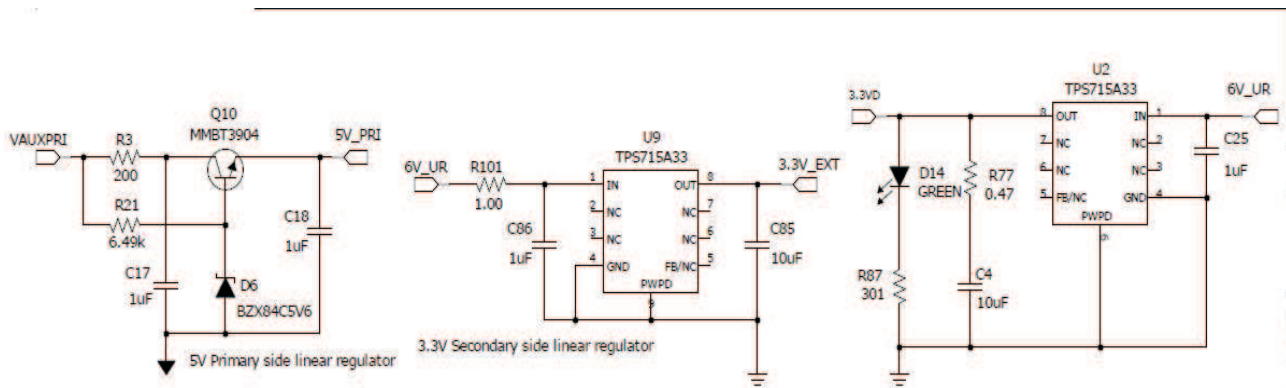


Figure 25. LDO Bias Circuits

A.3.3 Input Voltage Sensing Using Bias Transformer

As the controller is located on the secondary side, special approaches are required to obtain the input voltage information from the primary side for control needs. One approach is to use the main bias power supply transformer winding.

As shown in Figure 24, a sample-and-hold circuit is on the secondary side to sense the primary voltage. When switch Q9 turns on, D3 turns on by the negative voltage from divider R31 and R76. The voltage on the winding (6, 7) of bias transformer T2 charges capacitor (C71) to a negative voltage equal to V_{in}/N times the attenuator ratio of R31 and R76, (N is turns ratio of T2). When Q9 is turned off, D3 is turned off, and the voltage on C71 is held until next switching period. The voltage on C71 is proportional to the input voltage. U11 is used to invert the input negative voltage to positive output voltage scaled by R93 and R79. This input voltage monitoring approach is an optional for potential applications while not enabled in the EVM firmware.

A.3.4 Input Voltage Sensing Using Main Transformer

The sensing approach described in Section 12.3.3 is good to use in steady-state but not capable of fast transient sensing. This approach presents slow detection and slow response. Its advantage is less noise sensitive.

To improve input voltage sensing speed in real time, the main power transformer can be used. As shown in Figure 26, the approach takes the input voltage signal (VIN_CT) from the center tap of the main transformer secondary side windings, then scaling the signal to feed into UCD3138 EADC02. This EVM uses this sense structure when the converter is in startup, in steady-state, as well as in input voltage feed forward control. Particularly when use this structure for converter startup, the approach is called single-frame input voltage sensing. Single-frame here means one switching cycle. More details on how the main transformer is used to make input voltage sense can be found in Section 12.5.

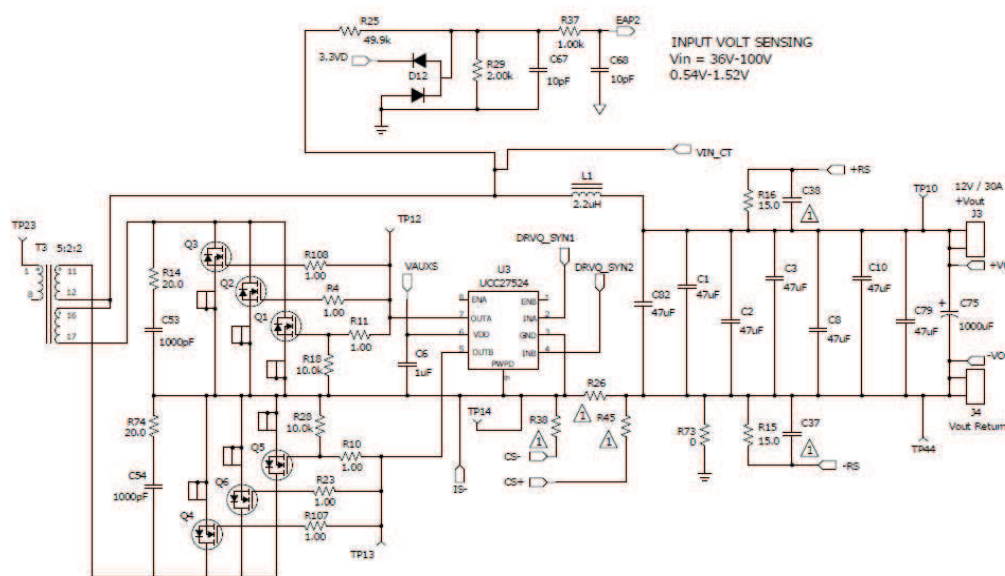


Figure 26. Input Voltage Sensing Using Main Transformer

A.3.5 Load Current Sensing by PCB Copper

To utilize the board area, this EVM uses copper trace (R26) to sense the output load current. The copper sensing related circuit is shown in Figure 27X. R41 and R43 are installed to feed the sensing signal to the current amplifier U10. With a low pass filter (C7, R54 and R20), the output voltage of the amplifier is of DC voltage in nature. The signal is then fed to AD13 of the controller. The amplifier gain can be set to 137 by choosing $R41 = R43 = 1k$, $R61 = 137k$.

AD13 is used to sense the load current, then the processor utilize the information for many applications, such as reporting the current to the host, calculating output power, implementing current sharing and over current protection.

The accuracy of sensing current with a copper trace is usually poor because the resistance of copper trace depends not only on the base copper thickness and plating, but also on the temperature of the copper. The base copper has a temperature coefficient of about 4000 PPM per degree C. Fortunately, the resistance can be measured and stored during manufacturing, and the temperature of the copper trace can be measured to compensate for temperature drift. The temperature of the copper trace is measured by a temperature sensor U11 (LM60C) then feed into UCD3138 through AD06. Please refer to Section 12.6.7 for temperature sensing.

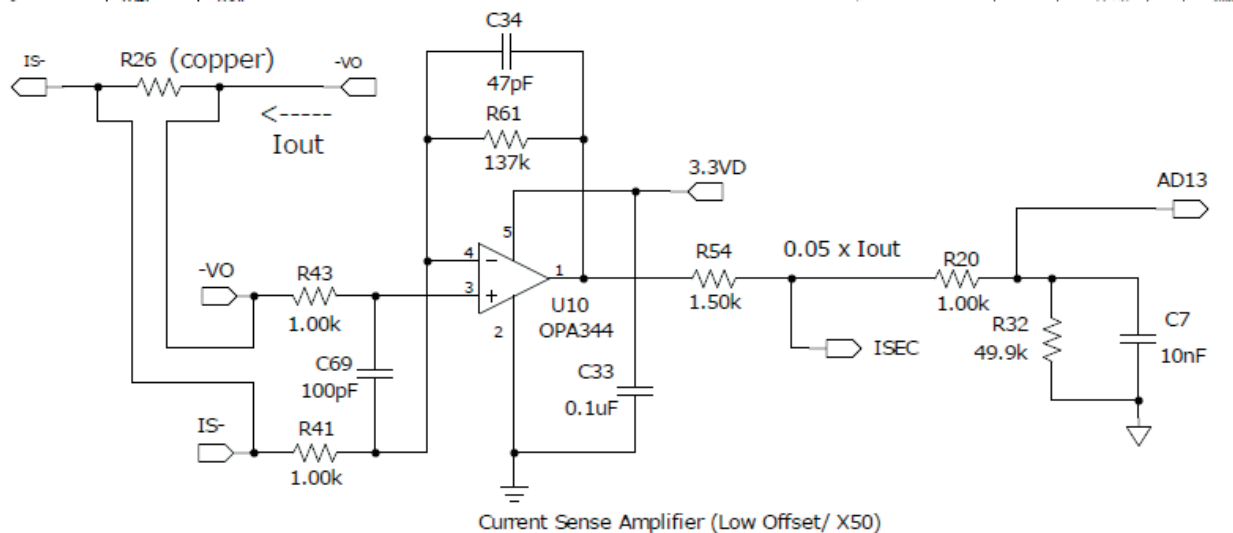


Figure 27. Load Current Sensing by PCB Copper

A.3.6 Load Current Sharing

UCD3138 supports three major current sharing techniques:

- Average Current Sharing, or PWM Bus Current Sharing
- Master/Slave Current Sharing,
- Droop Mode Current Sharing, or Analog Bus Current Sharing

This EVM uses the average current sharing. If interested in the other two sharing techniques, please contact TI for further assistance.

The average current sharing technique uses a share bus to balance and evenly distribute current on each paralleled converter. The share bus is called ISHARE in this EVM design. Hence, when making load current sharing, ISHARE from each board requires connecting together. ISHARE connection is located on P2 terminal pin 3 on the EVM board.

Figure 28 shows the load sharing module inside UCD3138. When enable the average current sharing, SW1 turns on. The ISHARE bus is on AD02 output which generates a voltage corresponding to the load current of that board. As all boards in share connected together by each of their own ISHARE, the voltage on EXT CAP (C19) is an averaged value representing a targeted sharing value for each converter output current. AD13, is used to measure the load current of each board in voltage, then compare to the voltage on ISHARE to adjust one's own output current level to match the targeted ISHARE value by DPWM duty cycle control.

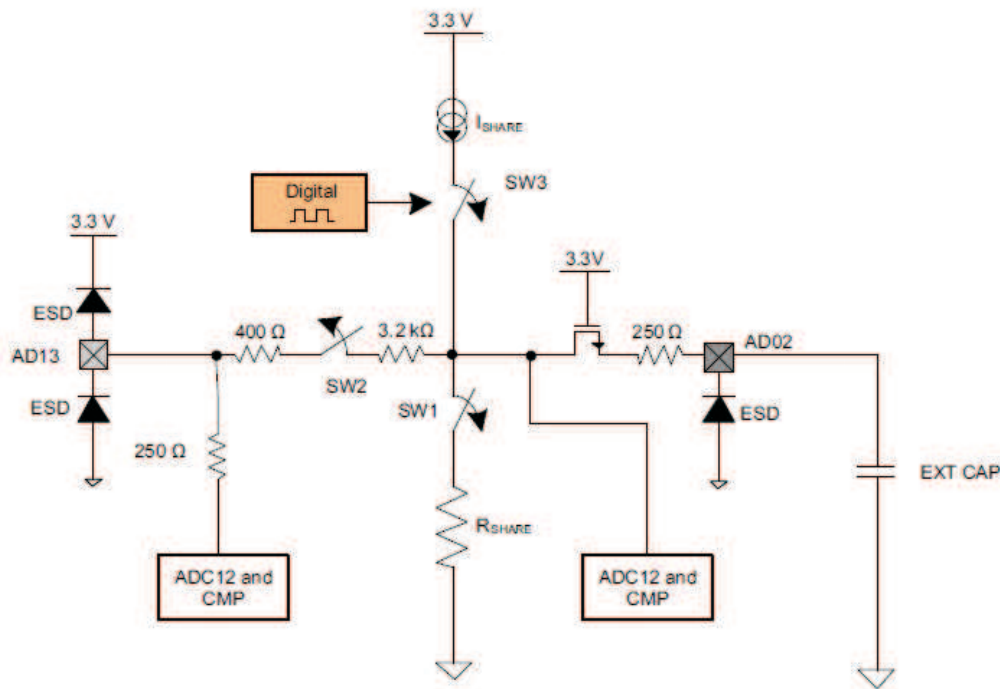


Figure 28. UCD3138 Load Sharing Module

A.3.7 Serial Port Interface

The schematic of the interface for the serial port (UART) is shown in Figure 29. The UART is able to provide real time debug and subsequently reduce code development time. It can also be used as a monitor for fast changing internal variables. The UART is not enabled in delivered EVM boards. Please contact TI to find how to enable this function.

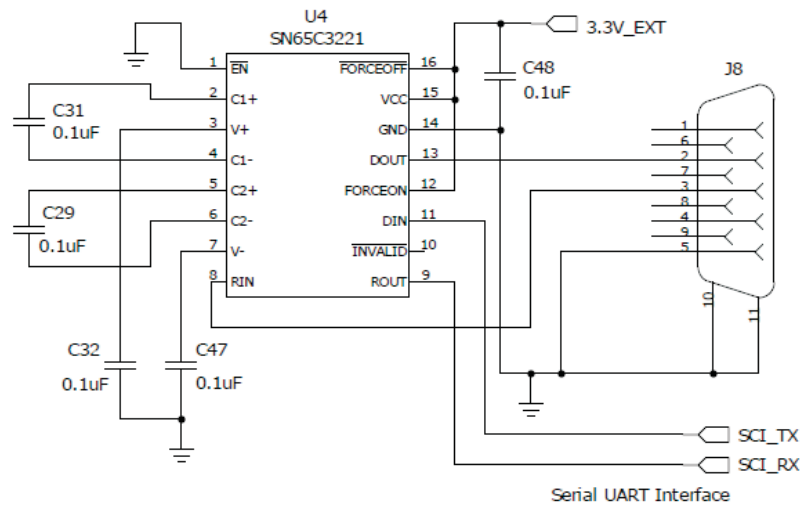


Figure 29. Serial Port Interface in the Converter

A.3.8 LED Indicators

Table 5. LED Status Lights

| REF DES | SILK SCREEN TEXT | FUNCTION |
|---------|------------------|--|
| D14 | | This light is on in green when 3.3VD is present on UCD3138. |
| D13 | VIN_OK | This light is on in red when input voltage ok. |
| D2 | FAILURE | This light is on in red when latch-off fault(s) present, currently OVP only. |
| D19 | P_GOOD | This light is on in green when the output voltage is within the thresholds defined by PMBUS_CMD_POWER_GOOD_ON and PMBUS_CMD_POWER_GOOD_OFF |

A.4 EVM Firmware – Introduction

The reference firmware provided along with the EVM is only intended to demonstrate basic HSFB converter control functionality as well as basic PMBus communication. The firmware can be used as an initial platform for particular applications. A brief introduction to the firmware is provided in this section.

A.4.1 Firmware Infrastructure Overview

The firmware includes one startup routine and three program threads. The startup routine is to make initialization to set up the controller to the targeted operation functions or status. Please contact TI to obtain the detailed initialization information.

The three program threads are (a) the Fast Interrupt (FIQ); (b) the Standard Interrupt (IRQ); and (c) the Background Loop, as shown in Figure 30.

- Fast Interrupt (FIQ)
 - Critical or time sensitive tasks are within the FIQ. Functionally, FIQ events are the highest priority and are addressed as soon as possible. It occurs every 4 switching- cycles, set by DPWM interrupt.
- Standard Interrupt (IRQ)
 - The majority of the firmware tasks occur during the IRQ. IRQ events occur synchronously every 100 μ s set by timer.
- Background Loop
 - Non time sensitive tasks are implemented in background loop. Background Loop items are addressed whenever FIQ and IRQ events are not handled.

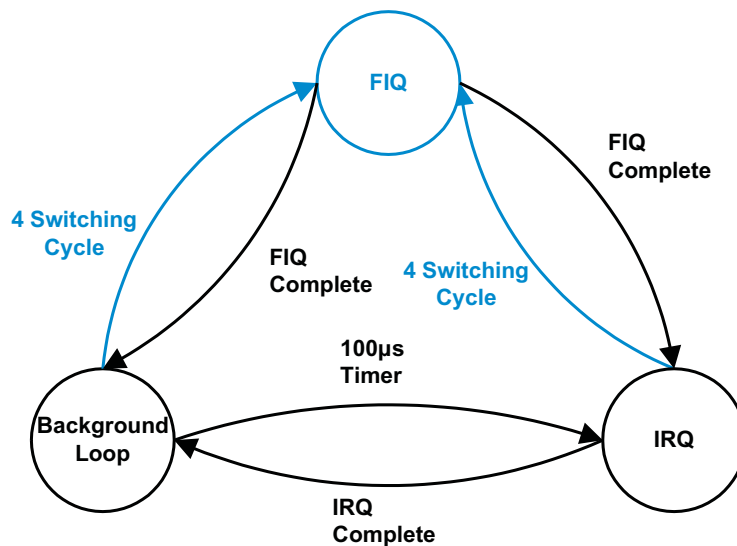


Figure 30. Firmware Structure Overview

A.4.2 Tasks within FIQ

The FIQ events are with the highest priority and are addressed as soon as possible. Critical or time sensitive tasks are in the FIQ. In the firmware uploaded into the EVM, the function called by the FIQ is Constant Power and Constant Current function.

There are two control loops in the EVM. Voltage Loop for Vout regulation; and Current Loop for constant current protection. Front End 0 and Filter 0 are for the voltage loop, Front End 1 and Filter 1 are for the current loop. In FIQ, the filter output of the two loops is compared. The loop takes control of the power stage is decided base on the larger output of the two filter-outputs.

The FIQ gets called to response every 4 switching cycles.

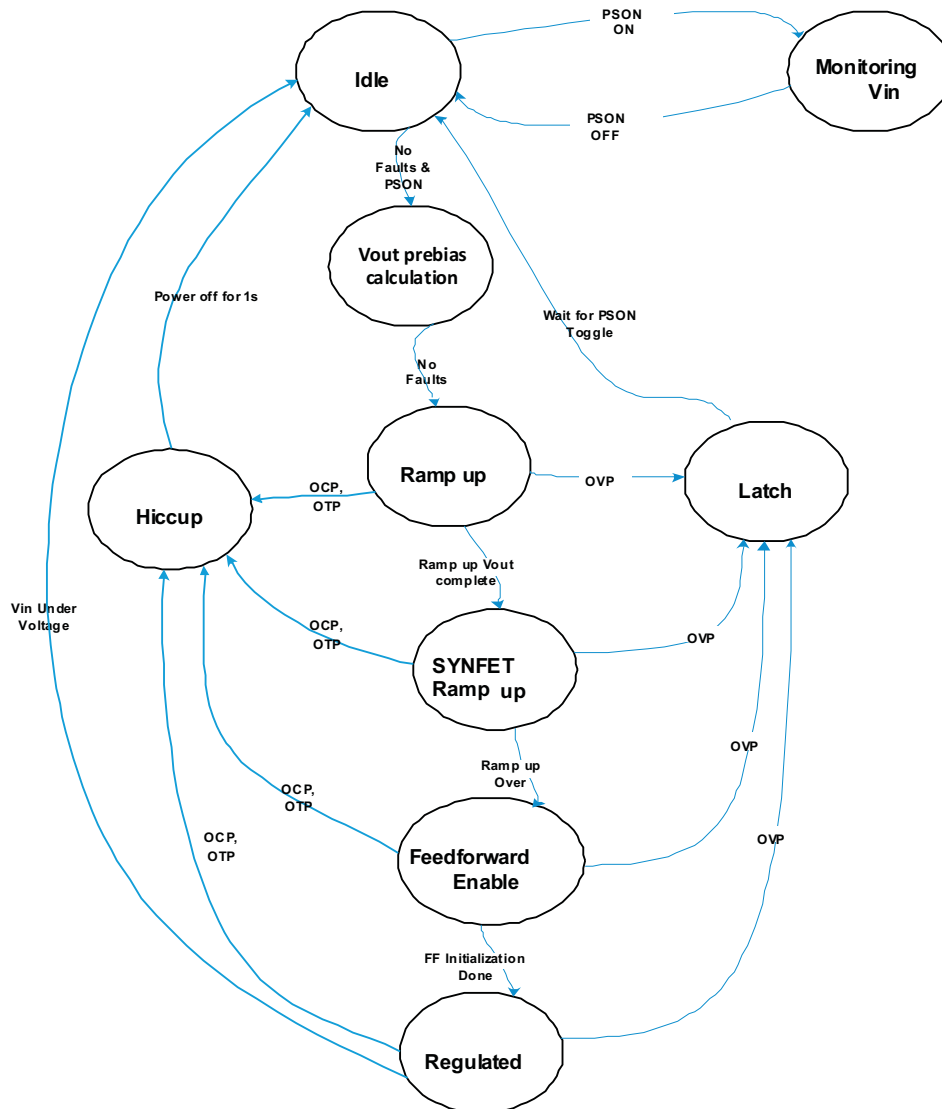


Figure 31. State Machine

A.4.3 Tasks within IRQ State Machine

Almost all firmware tasks occur during the IRQ. The only exceptions are the serial interface and PMBus tasks, which occur in the Background Loop; and the over current protection (OCP), which is handled by the FIQ. The IRQ is called to response every 100 μ s.

At the heart of the IRQ function is the power supply State Machine implemented with “switch” command. The State Machine has its structure as shown in Figure 31. At a higher level, this State Machine allows the digital controller to optimize the performance of the power supply, based on exactly what it is doing.

A.4.4 Tasks within Background Loop

The background loop handles all PMBus communication as well as process and transmit data through the UART. The data flash is managed with a dual-bank approach. This provides redundancy in the event of a power interruption during the programming of data flash. Once new data flash values have been written, a function called `erase_task()` is initiated in the background loop to erase the old values. The `erase_task()` continues to get called until all of the old DFLASH segments are erased. Erasing the data flash in segments allows the processor in the controller to handle other tasks instead of waiting for the entire data flash to be erased before doing anything else.

A.5 System Normal Operation

The EVM is designed to operate in PWM hard switching mode in normal operation conditions. At very light load condition, if needed, the burst operation can be enabled for EVM operation. Please contact TI to find how to enable this function.

On the other end of the operation, if the load power keeps increasing beyond the rated value, then an over load condition will occur. In such a case, the system will enter protection operation, first entering constant power constant current mode, then if load power still keeps increasing, this will trigger cycle-by-cycle current limit. Please refer to Section 12.6 to learn more about these protection functions.

The converter of this EVM is designed to work in the following manner.

- When V_{in} reaches above 22V, the auxiliary power supply turns on. The UCD3138 starts and uses the single-frame approach to check if V_{in} reaches 36V if S1 is on. If V_{in} reaches 36V or above, operation starts.
- The converter is in normal operation to regulate the output voltage at 12V nominally. As shown in Figure 32, Ch1 = TP13, Ch2 = TP25, Ch3 = TP23, and Ch4 = TP12, all referenced to the primary-side ground.
- When the load current reaches such a level to have full power as specified in a pre-determined constant power setting, say 360W, the output voltage to be regulated reduced, the higher the load current, the lower the output voltage regulation point, in this way, the constant power operation is achieved.
- The converter is controlled to keep operating in constant power mode until the load current reaches a pre-determined level, say 36A, then the operation enters the constant current mode. In this mode, Frond End 1 and Filter 1 takes control of the power stage and maintains the output current at the setting point 36A. If the controller sees a large current on the primary side, say over 14A, hardware cycle-by-cycle current limit function becomes active.
- Further increase load current will shift the primary side current peak value higher. When the peak values reaches a pre-determined level, the operation is in short circuit protection mode.

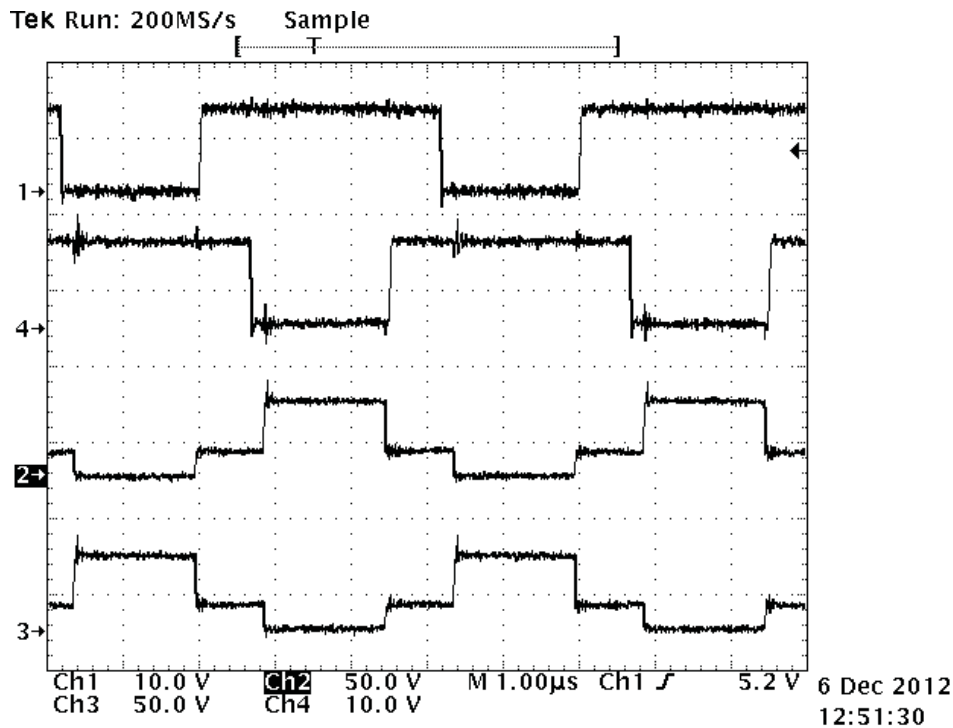


Figure 32. Normal Operation Switching Waveforms

A.5.1 Start-Up with Single-Frame Input Voltage Sensing

Before start up, the EVM uses a different way to sense the primary side voltage. It is called single-frame Vin sensing. In idle mode, two sets of single DPWM frames with 800ns width are sent, EADC2 are used to catch the second pulse from secondary and input voltage is determined. The sensing point can be programmed to get the best noise performance. The single-frame Vin sensing scheme is illustrated in Figure 33. Figure 34 shows test waveforms, where the green and the blue are two primary DPWM; the orange is VIN_SNS feed to EADC2. The purple is the transformer CT.

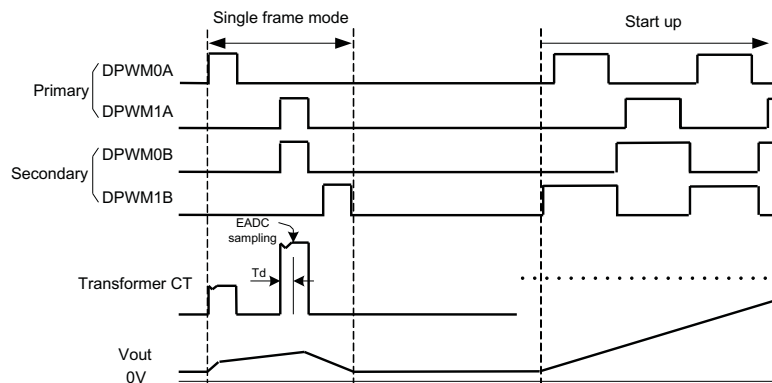


Figure 33. Input Voltage Sensing Using EADC2

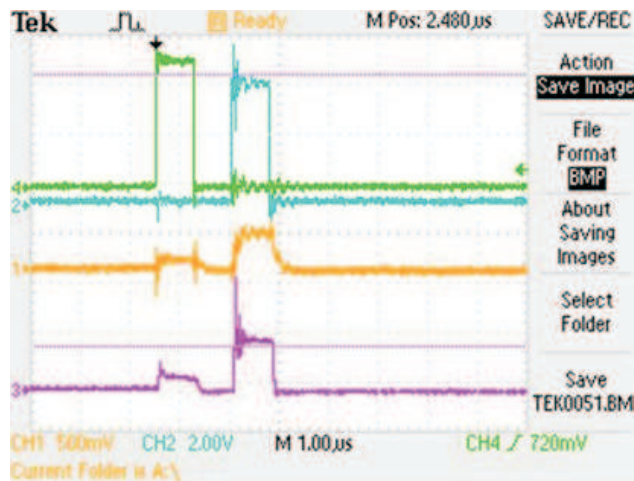


Figure 34. Single-Frame Approach Test

In normal operation control, the sensing hardware connection also serves the input voltage feed forward control, refer to Section 12.5.4.

A.5.2 Prebias Load and Load Synchronous Startup

When start a converter into pre-biased load condition, or start with two or more converters in parallel, special techniques are required since even a small difference from each output voltage may cause reverse current flow. The special technique, called Synchronous Startup, is used to enhance the parallel startup performance of UCD3138 controlled converters. This technique uses a GPIO pin as sync-pin which connects each board together to start at the same time then the output voltage difference from different converter is minimized.

A.5.3 Current Sharing Operation

To make two boards in current sharing operation, P2 pin 3 of each board is required to connect together as shown in Figure 35. P2 pin 3 serves as an “ISAHRE” connection, refer to Section 12.3.6. Figure 36 provides a test result, the yellow is output voltage, the other two channels are output currents from two paralleled EVM boards. The test was made with total load current change from 3A to 60A. The current sharing ratio in steady state at 60A-load is nearly perfect, i.e., close to 50%-50%. In the transient, the sharing difference is about 9.8A with settle down time about 560us. With the 95% load step change, the V_o overshoot and undershoot is about 0.4V on 12V, or about 3.5%

The current sharing operation is made possible in the steady-state. To share the load current in soft start time, it is recommended to use Synchronous Startup technique as described in Section 12.5.2. With this technique, the load current can still be shared to some degree since CPCC allows completing the soft start without shut down even if one converter in slight over load condition. Please contact TI to find how to set up Synchronous Startup.

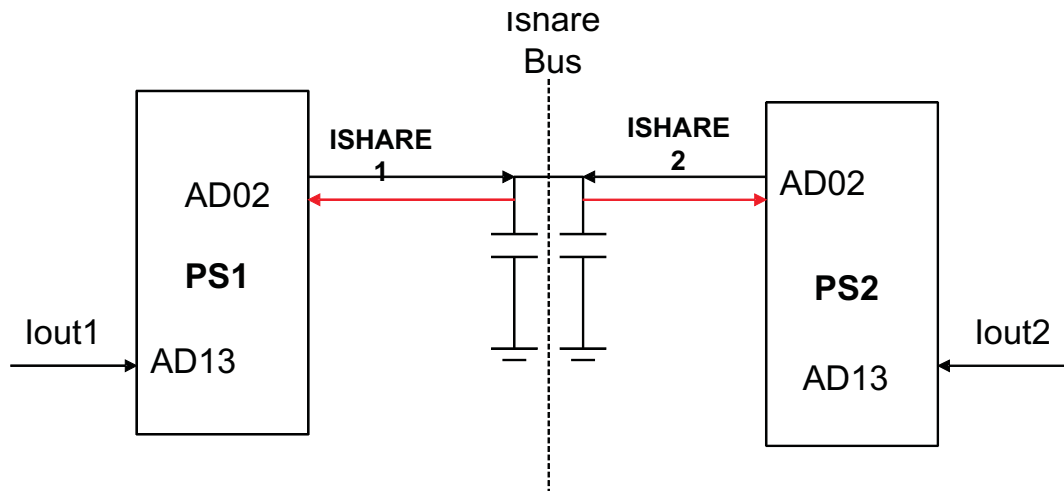


Figure 35. Current Sharing Operation



Figure 36. Current Sharing Test

A.5.4 Input Voltage Feed Forward Control

The input voltage feed forward control employed in the power converter control is to help to maintain output voltage regulation during input voltage high transient time. This technique can adjust the needed final duty cycle right with the input voltage change without go through normal feedback loop which usually has much longer timer delay in order to correct the output voltage error from input voltage transient. By ignoring the various losses, assuming output voltage 12V and unity transformer turns ratio, and assuming the converter secondary-side in CCM (as SR is in place), the relationship between input and output in a dc-dc forward type of converter, can be described by the duty cycle,

$$d = \frac{V_{OUT}}{V_{IN}} \quad (1)$$

Plot this equation, the relationship between input and output can be shown with the red curve in Figure 37.

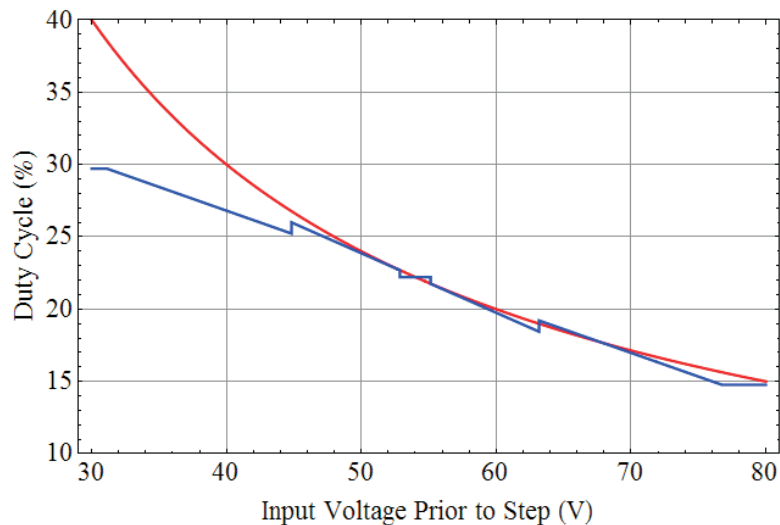


Figure 37. Duty Cycle Change in Feed Forward Control

In digital control, the duty cycle shown in the red-curve can be represented by a piecewise-linear approximation overlaid in the blue-curve. UCD3138 implements the blue-curve approximation with a non-linear multiplier as shown Figure 38 which shows the control functions implemented in UCD3138. In normal operation without input voltage transient, CLA2 output is unity. The DPWM is solely controlled by CLA1. When input voltage is in transient, CLA2 generates a multiplier based on input voltage change level which can be pre-programmed.

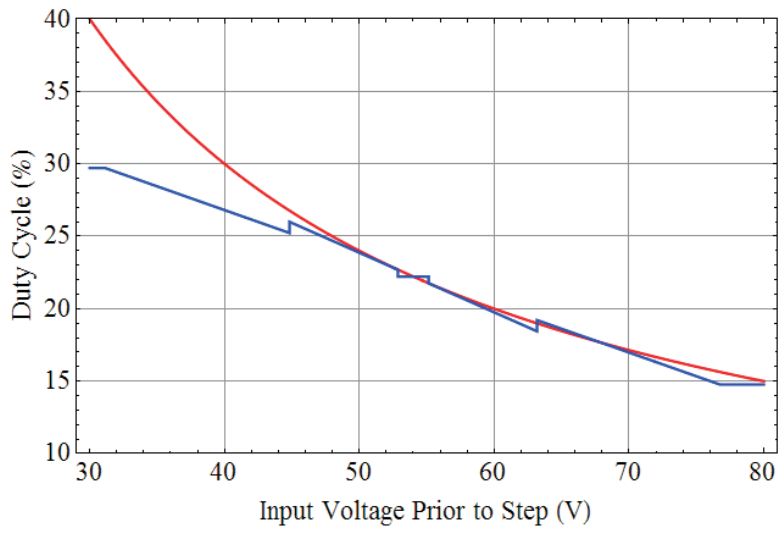


Figure 38. UCD3138 Digital Feed-Forward Control

On the control used in this EVM, the input voltage sense value is compared with Vref2, their difference, Vth, will set up the multiplier from CLA2 to CLA1 as below.

- If $-V_{th1} < V_{th} < V_{th1}$, CLA2 = Gain0, or Kp0
- If $-V_{th2} < V_{th} < -V_{th1}$, or, $V_{th1} < V_{th} < V_{th2}$, CLA2 = Gain1, or Kp1
- If $-V_{th2} > V_{th}$ or $V_{th2} < V_{th}$, CLA2 = Gain2, or Kp2

The above can be expressed as,

$$\text{Gain} = K_C + K_P \times (\text{VDAC} - V_{\text{in_sense}}) \quad (2)$$

In steady-state, Gain0 = Kc, where Kc can be described as a unity number although in practice it may be designed differently to match other scaled values.

During the input voltage transient, nonlinear gain is generated to achieve desired duty cycle by feed forward control approximation.

As the control algorithm is of symmetrical characteristics from $\pm V_{th1}$ and $\pm V_{th2}$, an equilibrium point is required to be established. From practice such as in 48V-telecom application, this point may be initially selected at VIN0 = 48V. During the operation with different input voltage, a new equilibrium point will be re-established corresponding to that input voltage.

In this EVM design, Vin_sense signal is from VIN_CT as shown in Figure 26 and its relationship to VIN is expressed as,

$V_{\text{in_sense}} = (V_{\text{in}}/N) \times R_{29} / (R_{25}+R_{29}) = k \times V_{\text{in}}$, where $k = 0.0154$, and N is the turns ratio of Transformer T3.

A.5.5 Feed Forward Function Test

Load = 1A, Vin from 40V to 58V, Vin slew rate 20V/us, Vo maximum shift 0.68V, recovery time 50us. In Figure 39, the purple is Vout and the yellow is Vin. In Figure 40, the green is primary side DPWM and the yellow is Vin.

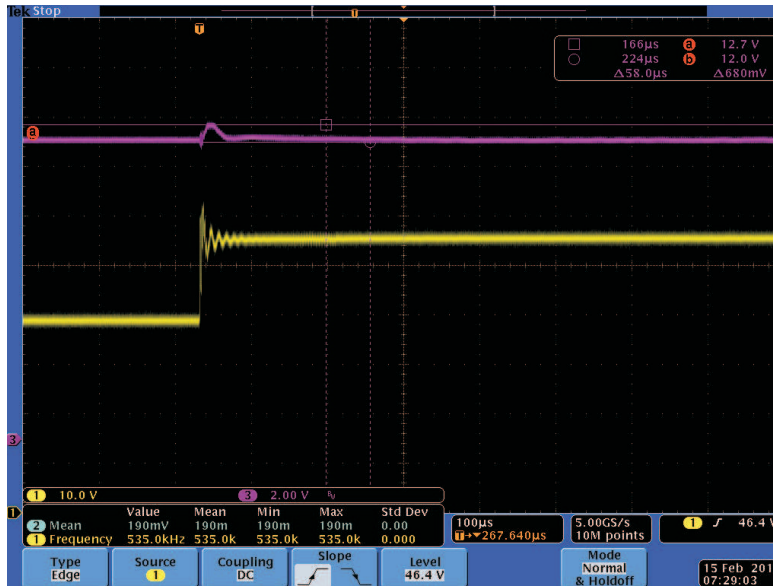


Figure 39. Vo Change from Digital Feed Forward Control

A.5.6 Light Load Operation

At light load, the burst operation can be enabled when the switching duty cycle is small. The significant benefit from this operation is the reduction of the power losses. The associated disadvantage is of higher output voltage ripple in steady-state and of larger output voltage dip in load demanding transient. But the higher ripple and the larger dip can be solved especially with digital control of its convenience and flexibility. For example, non-linear control from digital control can solve the large dip during load transient. The higher ripple can also be reduced by narrowed duty cycle on/off limit for burst operation control.

Figure 41 shows the burst operation timing diagram with UCD3138. When the controller detected light load condition, the operation is enabled into Light-Load-Enable (LLE) by firmware. When load condition is changed to heavy, CLA can generate a large gain to adapt the load change and minimize the output voltage drop although the operation is still in LLE mode. If the load keeps heavy for certain time, light load will be terminated by the firmware.

The burst operation mode is disabled in the EVM. Please contact TI to know how to enable this feature.

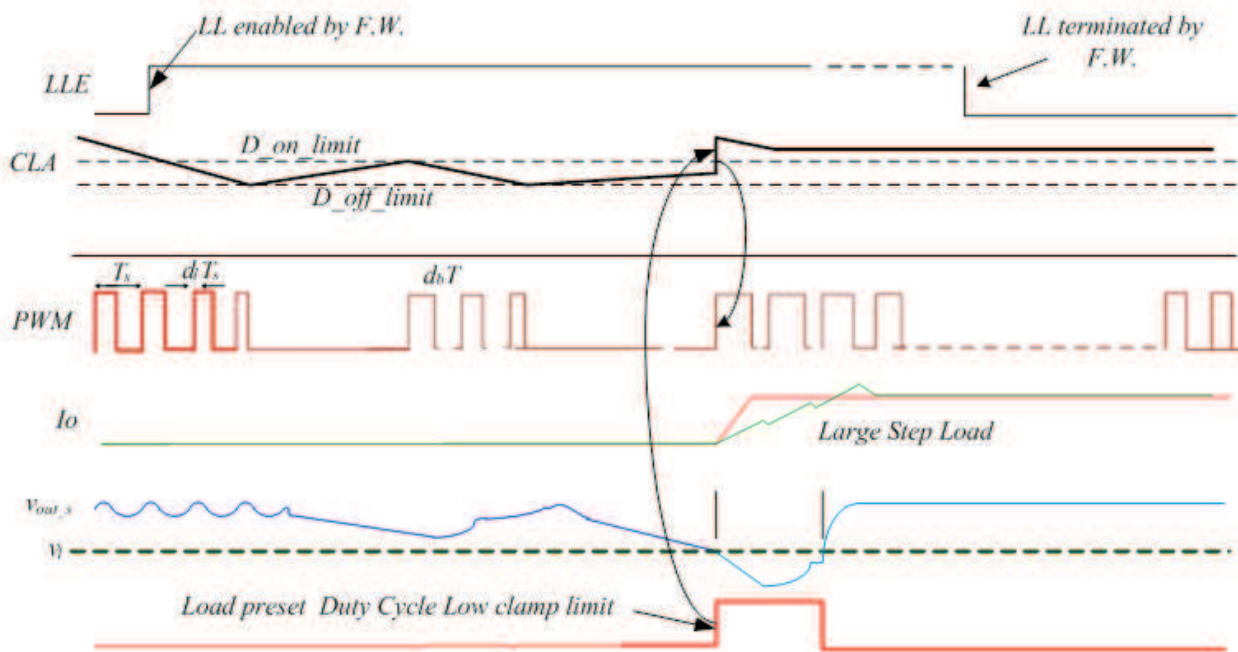


Figure 41. Burst Operation Timing Diagram

A.6 System Operation in Protection

A.6.1 Faults and Warnings

The system comes equipped with a variety of programmable fault and warning options. In section 12.3.8, Table 5 lists the LEDs used to indicate a fault. Table 6 below shows the basic faults and warnings available in the EVM along with the corresponding action taken by these events. Each of these parameters can be modified through the GUI.

Table 6. Faults and Warnings

| SIGNAL | TYPE | WARNING | FAULT RESPONSE |
|-------------|-------|---------|-------------------------|
| VOUT | Over | Report | Report & Latch off |
| | Under | Report | Report |
| VIN | Over | Report | Report & Latch off |
| | Under | Report | Report & Latch off |
| IOUT | Over | Report | Report & Latch off |
| IIN | Over | Report | Cycle by cycle limiting |
| Temperature | Over | Report | Report & Latch off |

The GUI reporting includes appropriate setting of the PMBus alert line, status byte and status word. Faults and warnings can be reset by toggling the unit off and then on. Alternatively, as long as the system does not latch off, the “Clear Faults” button can also be used to clear any faults or warnings. Refer to Figure 42 which is from the Designer GUI Monitor tab. More details can be found in Section 13.

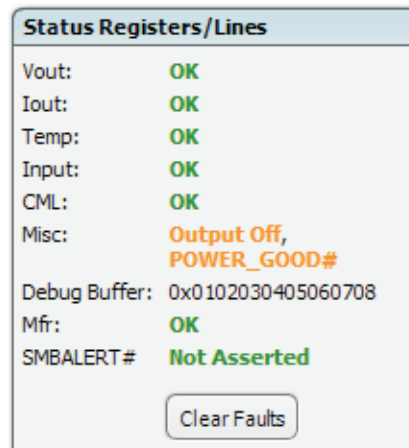


Figure 42. Faults and Warnings

A.6.2 Constant Power Constant Current Operation

Both hardware and firmware in this EVM supports Constant Power Constant Current, or CPCC operation. Figure 43 illustrates the behavior of the output voltage and output current (V_{OUT} vs. I_{OUT}). However, the EVM comes pre-programmed with a constant power threshold of 360 W and a constant current threshold of 36 A. Some of the limits are adjustable through the GUI and new setting can be saved to data flash. The maximum hardware capability is to limit the current within 36A. Figure 44 shows the GUI interface to these controls with the default values. The CPCC can be enabled or disabled through GUI. Details can be found in Section 13.4.2.

After the output power reaches the set point, V_{out} starts to drop while the power keeps the same which means the current may increase. The power stage stays on and it won't enter latch mode. When the current loop filter output (Front End 1 and Filter 1) is larger than the voltage loop filter output (Front End 0 and Filter 0), the current loop takes control of the power stage and output voltage starts in hiccup operation state. In hiccup state, the power stage stays on for 1s, and then goes to idle state and try to turn on again. If the load is reduced, the power stage will go to regulated state. If the load current is still high, the output voltage goes to hiccup state again. Only OVP will take the power stage to latch-off state. OTP, OCP, and constant current will take the power state to hiccup state. In hiccup state, the power state turns on automatically. In latch state, toggle off the PSON switch is needed or recycle the input power.

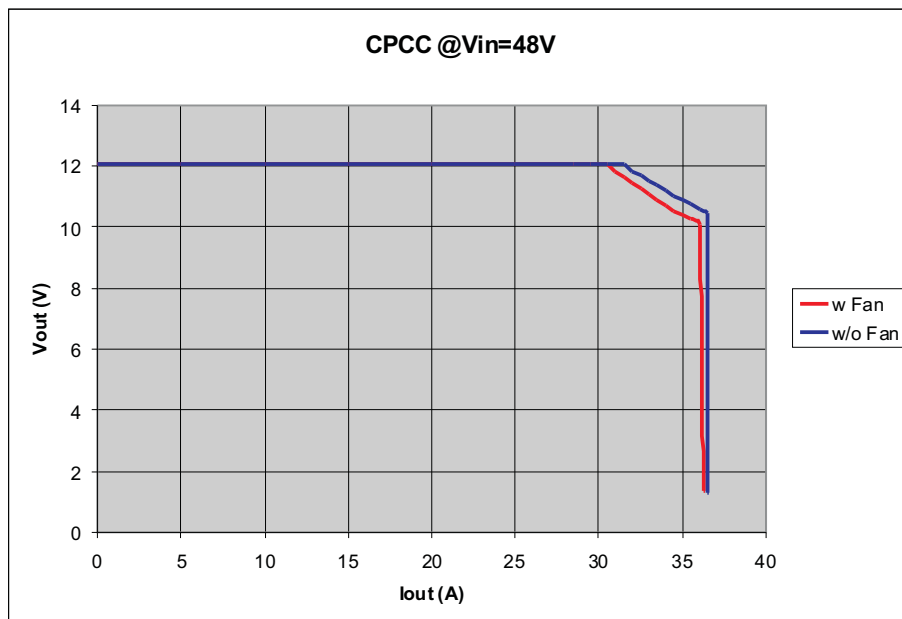


Figure 43. Constant Power Constant Current Operation

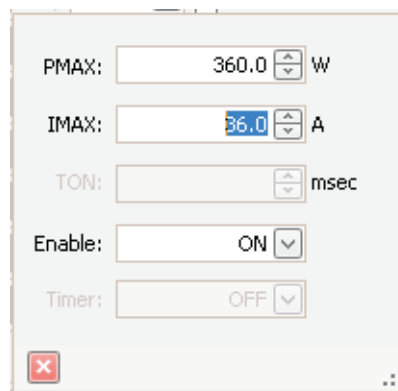


Figure 44. CPCC Default Values and Adjustable through GUI

A.6.3 Cycle-By-Cycle Current Limit

Cycle by cycle current limit is made to the primary side input current. The current is sensed by current transformer T1. The sensing circuit is shown in Figure 45; also refer to full schematics of Figure 1 and power stage Figure 23. The current signal is fed into AD04 and compared to a programmable threshold on a cycle-by-cycle basis. Whenever this current exceeds the threshold the active DPWM waveforms are truncated. The cycle-by-cycle current limit is mainly used to the primary current to limit its peak within pre-determined value, default as 16A.

As AD04 is a simple voltage comparator, external current slope compensation circuit may be needed in order to minimize the sub-harmonics normally existing in peak current mode control including cycle-by-cycle current limit. An example circuit is shown in Figure 46. More detail on this circuit can be found in "Modeling, Analysis and Compensation of the Current-Mode Converter", (TI Literature Number SLUA101).

In case the peak current mode control is employed in an application, the peak current mode control should be made through Front End 2 (EADC2) instead of using AD04. Front End 2 has build-in current slope compensation (RAMP) as shown in Figure 47 which does not require external slope compensation.

UCD3138 can balance two pulses in a switching cycle with the same width. In UCD3138RHA, this feature exists in the DPWM module on its two outputs, for example between DPWM0A and 0B, but not available on the interconnection matrix. Then this EVM is not able to balance the pulse width in a switching cycle. If this feature is preferred, please contact TI for technical assistance.

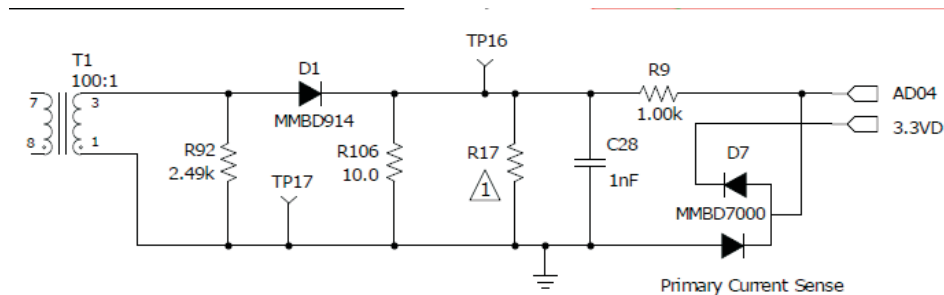


Figure 45. Cycle-by-cycle Current Limit Sensing Circuit

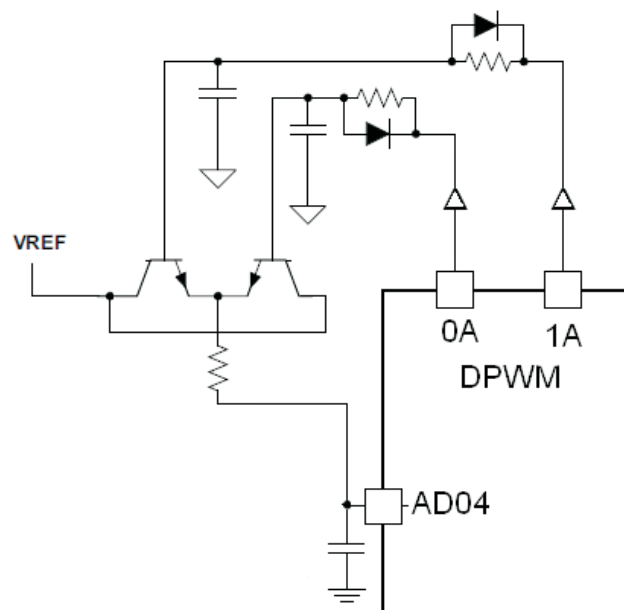


Figure 46. An Example of External Slope Compensation

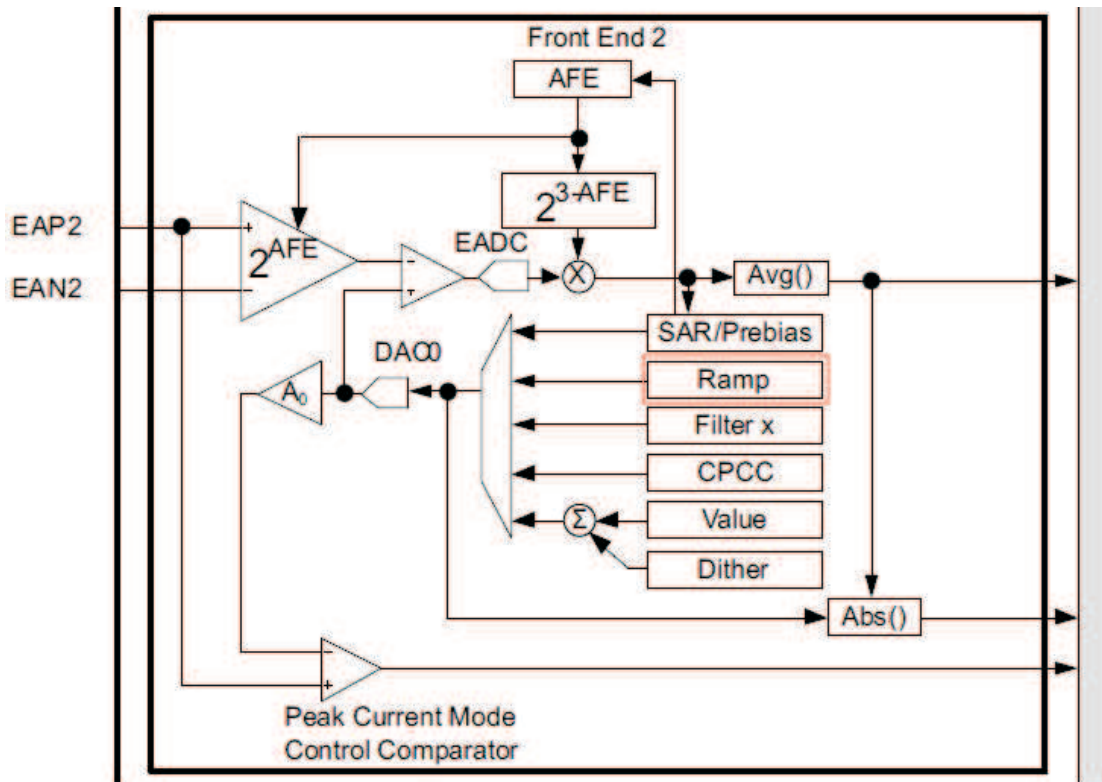


Figure 47. Peak Current Mode Control with Front End 2

A.6.4 Short Circuit Protection

Load short circuit protection is mainly based on the secondary side current sensing when the load current is beyond a 36A by default. In short circuit protection the output voltage is in hiccup state.

Figure 48 shows a test results with the conditions: short circuit test at 30A load, Vout (Ch1), Ipri (Ch 2), and Vin (Ch 3)

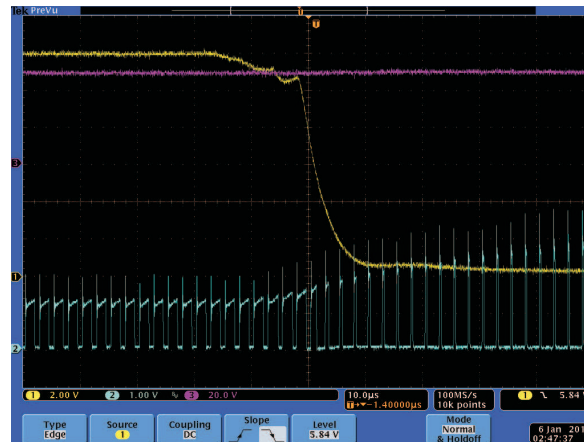


Figure 48. Short Circuit Protection Test

A.6.5 Output Over Voltage

Output over voltage detection and protection is through AD03, refer to Figure 1 and Figure 23. When output over voltage is detected, the switching pulses will be disabled and the board will be in latch-off until recycle the input power or toggle the switch S1.

A.6.6 Input Over Voltage

The input over voltage is detected based on the main power transformer winding as described in Section 12.3.4. Currently in the EVM delivered, input voltage is detected and the firmware provides warning to the Designer GUI. Please contact TI if need OVP protection.

A.6.7 Over Temperature

Over temperature includes UCD3138 internal temperature sensing and external added temperature sensing. The external over temperature condition is determined by a temperature sensing element on U13, LM60C. The temperature signal is fed into the controller through AD06. U13 is located on board top side next to the current sensing copper. Then it is sensing the temperature of secondary-side board temperature. In addition to the over temperature protection, this temperature information is used to compensate the copper current sensing.

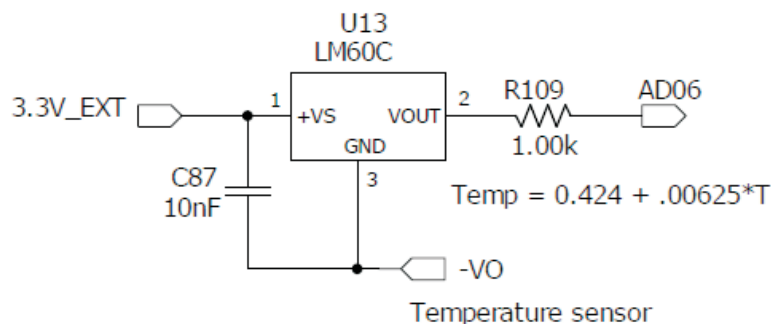


Figure 49. Temperature Detection Circuit

A.7 Loop Compensation Using PID Control

PID control is usually used in the feedback loop compensation in digitally controlled power converters. We will describe several aspects how to use PID control.

A.7.1 Digital PID Coefficients Transformation to Poles and Zeros in s-Domain

PID control in UCD3138 CLA for control loop is formed in the following equation in z-domain:

$$G_c(z) = K_P + K_I \frac{1+z^{-1}}{1-z^{-1}} + K_D \frac{1-z^{-1}}{1-\alpha \times z^{-1}} \quad (3)$$

If Equation (3) is converted to the s-domain equivalent using the bilinear transform, the result has two forms. One is with two real zeros and one real pole:

$$G_{cz}(s) = K_0 \frac{\left(\frac{s}{\omega_{z1}} + 1\right) \left(\frac{s}{\omega_{z2}} + 1\right)}{s \left(\frac{s}{\omega_{p1}} + 1\right)} \quad (4)$$

K_0 is the gain of the frequency domain pole at origin, and K_0 is also represented as the angular frequency when the integrator Bode plot gain crosses over with 0-dB. By the way, K_0 can be used as a method for initially designing the feedback loop compensation, refer to [5] for more details.

The second way is when the two zeros are possibly presented with complex conjugates and in such a case,

$$G_{cz}(s) = K_0 \frac{\left(\frac{s^2}{\omega_r^2} + \frac{s}{Q \times \omega_r} + 1\right)}{s \left(\frac{s}{\omega_{p1}} + 1\right)} \quad (5)$$

Two complex conjugate zeros are expressed as,

$$\omega_{z1, z2} = \frac{\omega_r}{2 \times Q} \left(1 \pm j\sqrt{4 \times Q^2 - 1}\right) \quad \text{and} \quad j = \sqrt{-1} \quad (6)$$

$$\omega_r = \sqrt{\omega_{z1} \times \omega_{z2}} \quad (7)$$

$$Q = \frac{\sqrt{\omega_{z1} \times \omega_{z2}}}{\omega_{z1} + \omega_{z2}} \quad (8)$$

The factor of Q is in the range of 0 to infinite. The two complex conjugate zeros become the two real zeros when Q is not greater than 0.5.

$$Q \leq 0.5 \quad (9)$$

Hence, Equation (4) is actually a special form of Equation (5). In this sense, Equation (5) can be used in either case across the range of Q.

A low pass filter usually exists in a control loop of its feedback path. The low pass filter adds a pole to the loop,

$$H_{CS}(s) = K_{CS} \frac{1}{\frac{s}{\omega_{PCS}} + 1} \quad (10)$$

The close loop transfer function is then shown as below:

$$G_{CS}(s) = \frac{G_M(s) \times G_{PID}(s)}{1 + G_M(s) \times G_{PID}(s) \times H_{CS}(s)} \quad (11)$$

where GM(s) is the control plant transfer function. For example, GM(s) can be the transfer function associated to the modulator in an HSFBC converter.

The parameters can be calculated with the assumption of sensor sampling cycle T_s much smaller than the corresponding time constant of the voltage loop bandwidth, T_C . A rule of thumb is to choose the sampling frequency to meet

$$T_s \leq 0.05 \times T_C \quad (12)$$

When the above assumption is true, the delay effect from the sampling (usually with zero order hold or ZOH) can be ignored and the parameters can be determined after we know where the poles and zeros should be positioned. Table 7 summarizes the poles and zeros in a form to relate z-domain to s-domain.

$$K_P = \frac{K_0 \times (\omega_{p1} \times \omega_{z1} + \omega_{p1} \times \omega_{z2} - \omega_{z1} \times \omega_{z2})}{\omega_{p1} \times \omega_{z1} \times \omega_{z2}} \quad (13)$$

$$K_I = \frac{K_0 \times T_s}{2} \quad (14)$$

$$K_D = \frac{2 \times K_0 \times (\omega_{p1} - \omega_{z1}) \times (\omega_{p1} - \omega_{z2})}{\omega_{p1} \times \omega_{z1} \times \omega_{z2} (T_s \times \omega_{p1} + 2)} \quad (15)$$

$$\alpha = \frac{2 - T_s \times \omega_{p1}}{2 + T_s \times \omega_{p1}} \quad (16)$$

Table 7. Poles and Zeros from PID Coefficients

| System Name | Transfer Functions |
|--|--|
| Complex Zeros (K_0, f_z, Q_z, f_p) | $\frac{s^2}{(2 \times \pi \times f_z)^2} + \frac{s}{2 \times \pi \times f_z \times Q_z} + 1$ $\frac{s}{2 \times \pi \times K_0} \times \left(\frac{s}{2 \times \pi \times f_p} + 1 \right)$ |
| Real Zeros (K_0, f_{z1}, f_{z2}, f_p) | $\left(\frac{s}{2 \times \pi \times f_{z1}} + 1 \right) \times \left(\frac{s}{2 \times \pi \times f_{z2}} + 1 \right)$ $\frac{s}{2 \times \pi \times K_0} \times \left(\frac{s}{2 \times \pi \times f_p} + 1 \right)$ |
| Device PID (K_p, K_i, K_d, α) | $1000 \times \left(K_p + K_i \times \frac{1+z^{-1}}{1-z^{-1}} + K_d \times \frac{1-z^{-1}}{1-\alpha \times 2^{-8} \times z^{-1}} \right) \times 2^{-SC} \times K_{COMP} \times 2^{-19} \times \frac{1}{2^4 \times (PRD+1)}$ |

A.7.2 Tuning PID Coefficients for Loop Compensation

When making fine-tune adjustments to the feedback control loop, one would like to know each parameter in PID how to affect the control loop characteristics without going through complicated description of the above equations. Table 8 below helps this and visually shown in Figure 50.

Table 8. Tuning PID Coefficients

| CONTROL PARAMETERS | IMPACT ON BODE PLOT |
|--------------------|---|
| K_p | Increasing K_p |
| | Pushes up the minimum gain between the two zeros. |
| | Moves the two zeros apart. |
| K_i | Increasing K_i |
| | Pushes up integration curve at low frequencies. |
| | Moves the first zero to the right. |
| K_d | Increasing K_d |
| | Shifts the second zero left. |
| | Doesn't impact the second pole. |
| α | Increasing α |
| | Shifts the second pole to the right. |
| | Shifts the second zero to the right. |
| $T_s = 1 / f_s$ | Increasing the sampling frequency f_s : |
| | Causes the whole Bode plot to shift to right. |

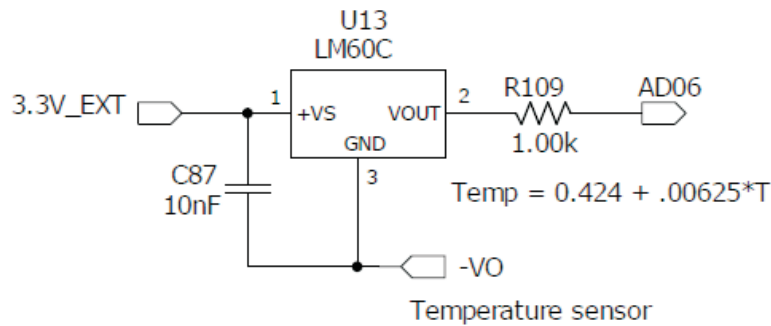


Figure 50. Tuning PID Parameters

A.7.3 Measuring the Control Loop

The control loop measurement can be made by injecting frequency sweep signal across R16. The connections can take advantage of P2 pin 1 and TP10.

A.8 Evaluating the EVM with GUI

Collectively, the GUI is called Texas Instruments Fusion Digital Power Designer. The GUI serves the interface for several families of TI digital control IC's including the family of UCD31xx, i.e., UCD3138 as its one member. The GUI can be divided into two main categories, Designer GUI and Device GUI. In the family of UCD31xx, each EVM is related to a particular Designer GUI to allow users to re-tune/re-configure a particular EVM in that regarding with existing hardware and firmware. Device GUI is related to a particular device to access its internal registers and memory cells.

UCD3138HSFBEM-029 is a standalone board where UCD3138RGH 40-pin device is placed. The firmware to control this converter is downloaded into this board through Device GUI. How to install the GUI is described in the user's guide "Using the UCD3138CC64EVM-030 (TI Lit#, SLUU886)". The designer GUI is installed at the same time when installing the Device GUI.

A.8.1 Graphical User Interface (GUI)

As mentioned above, there are two types of graphical user interfaces (GUI), one is Device GUI, and the other is Designer GUI. The Device GUI is sometimes called low level GUI. From the Device GUI, device's registers are accessed if the device is in the ROM mode and the PMBus communication is established. This GUI should be used to download the code when the device is blank at the first programming. Also, at the flash mode, a customer can send PMBus commands to read or write the data. The Designer GUI is an interface between a host and a user's board. It supports some of PMBus commands for configuration, monitoring and design such as loop compensator built in the UCD3138 digital controller.

A.8.1.1 13.1.1 Hardware Setup

The board hardware connection is overall the same as shown in Section 5.2 and Figure 4 while shown in Figure 51 again. The addition to the setup is to connect USB-to-GPIO to the board. The ribbon cable connects to J6 and the USB cabled connects to a host PC computer. The remaining connections are described again in the below.

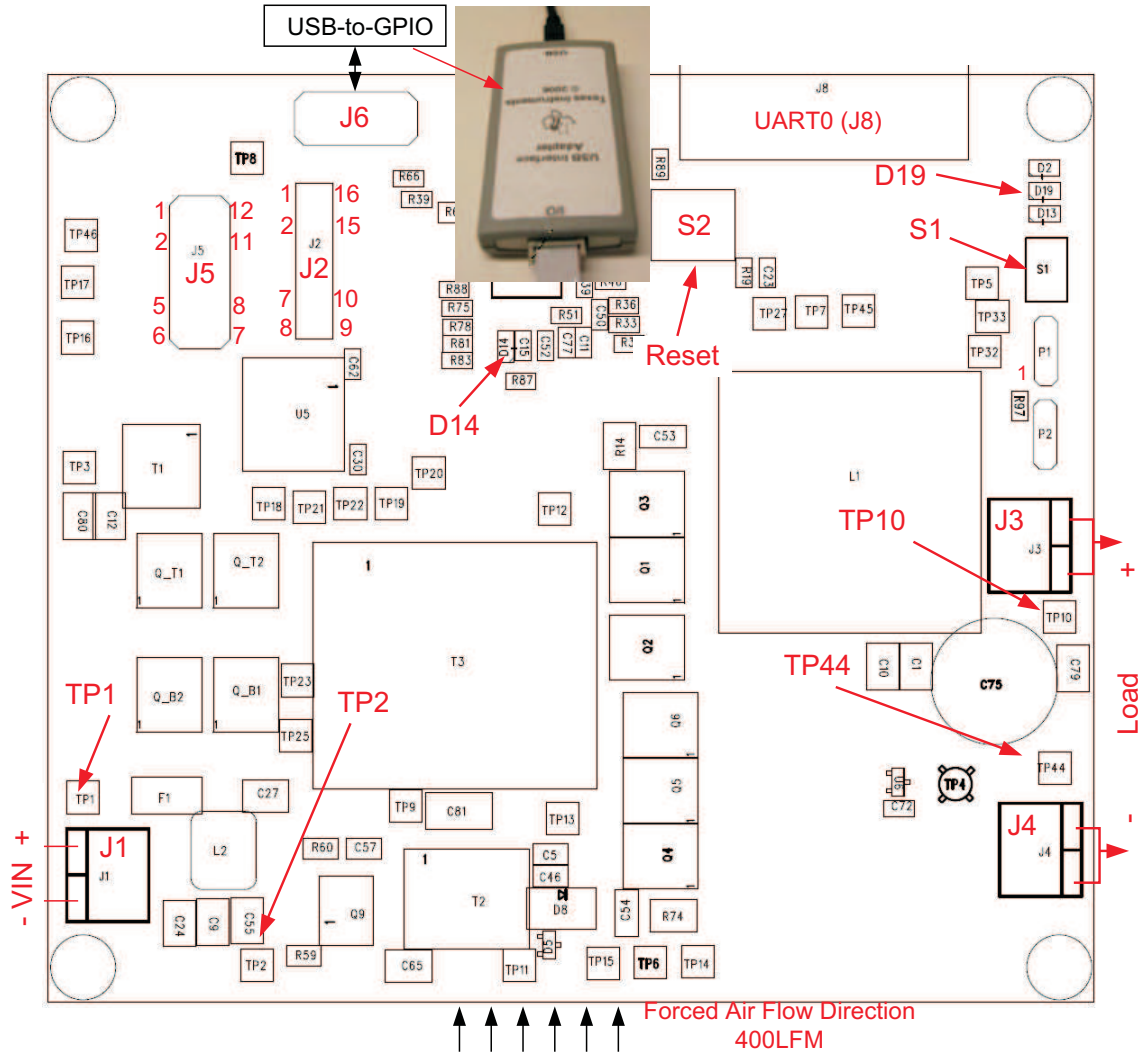


Figure 51. Test Setup

- Refer to Figure 51 for basic hardware connections. The required equipment is listed in Section 5.1.
- Before making electrical connections, visually check the boards to make sure no shipping damage occurred.
- Connect the DC voltage source to J1-1 (+) and J1-2 (-). Set up the DC output voltage in the range specified in Table 1, between $36 V_{DC}$ and $72 V_{DC}$; set up the DC source current limit 12A.
- Connect an electronic load with either constant current mode or constant resistance mode. The load range is from zero to 30A.
- Connect USB-to-GPIO ribbon cable to J6 and connect USB-to-GPIO USB cable to a host PC computer.
- Check and make sure the jumpers are installed correctly on J2 and J5.
 - J2 should be jumped across to connect its 1-16, 2-15, 7-10, and 8-9.
 - J5 should be jumped across to connect its 1-12, 2-11, 5-8, and 6-7.

WARNING

Follow the connections correctly to avoid possible damages

- It is recommended to use the switch S1 to turn on the board output after the input voltage is applied to the board. Before applying input voltage, make sure the switch, S1, is in the “OFF” position.
- If the load does not have a current or a power display, a current meter or low ohmic shunt and DMM will be needed between the load and the board for current measurements.
- Connect a volt-meter across the output connector and set the volt-meter scale 0 to 15V on its voltage, DC.

A.8.1.2 GUI Installation

GUI software can be downloaded from the TI website, www.ti.com. The software should be installed in the host PC before it is executed. More details about the TI GUI, which is called TI Fusion Digital Power Designer (DFPD), can be found in its user’s guide/manual. Please contact TI to get this user’s guide/manual. After the GUI installation, the Guide can be found in the Designer GUI of its real time “Help”.

“Help” > “Documentation & Help Center” > “UCD3138”

Copy the TI Fusion Digital Power Designer zip file and unzip the file TI-Fusion-Digital-Power-Designer-xx.zip to get installer TI-Fusion-Digital-Power-Designer-xxx.exe. The xxx in the file name refers to the GUI release version.

Double click the installer TI-Fusion-Digital-Power-Designer-xxx.exe and follow the straight forward instructions to finish the installation. Normally, you need accept all the installation defaults. In order to get all GUI functions, all boxes under Select Additional Tasks should be checked, shown in Figure 52.

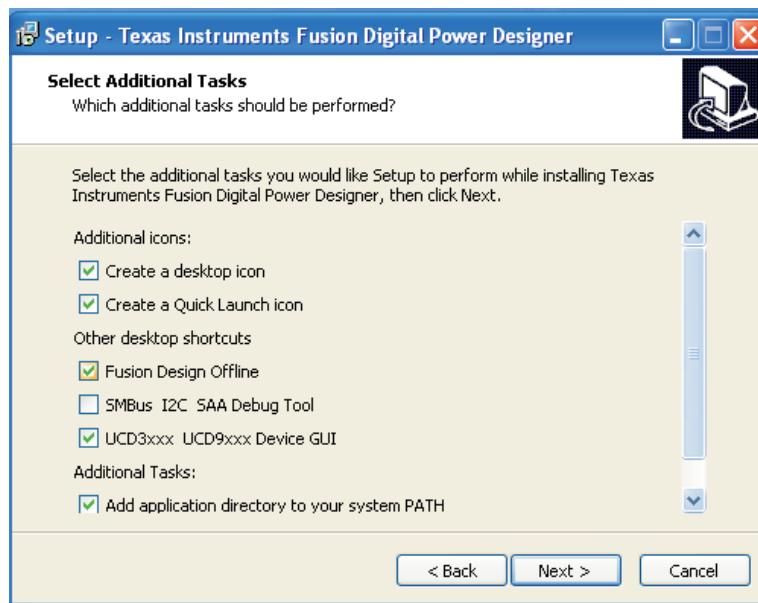


Figure 52. GUI Installation

After the installation, a quick launch button is created next to the start menu which contains shortcuts to commonly used applications. Figure 53 shows the icon of TI DFPD after the installation. Some other icons such as UCD3K Device GUI are also displayed on the desktop. For more information on the GUI installation, one can refer to UCD3138CC64EVM-030 user’s guide.



Figure 53. GUI Shortcut Location

A.8.1.3 USB-to-GPIO Adaptor Connection

CAUTION

Shut off DC power source before connection to avoid electrical shock!

Connect one end of the ribbon cable to the module, and connect the other end to the USB-to-GPIO (HPA172) interface adapter. Connect the Mini connector of the USB cable to the USB interface adapter, and connect the other end to the USB port of the host computer.

A.8.1.4 Launch the Designer GUI

Click the Quick Launch Shortcut icon located next to the start menu. The GUI starts to look for the attached device attached to the PMBus. If the device is found and the communication is established successfully, one should see a screen that looks similar to Figure 54. In the following we will describe how to use the GUI to evaluate the module.

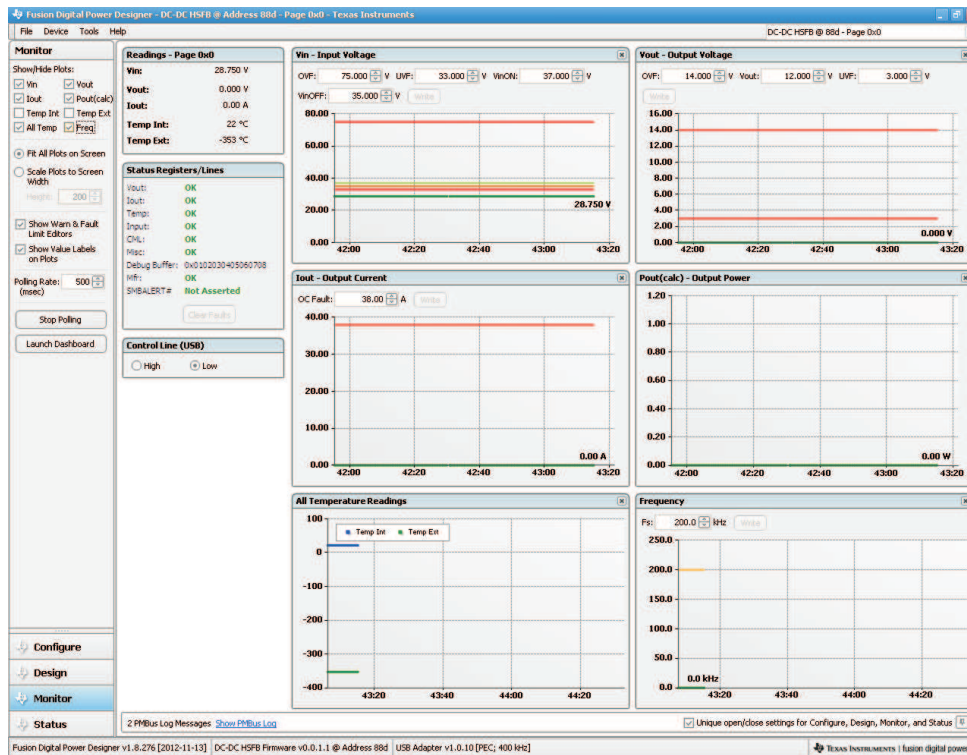


Figure 54. Designer GUI Overview

A.8.1.5 Designer GUI Overview

The Designer GUI has four tabs, as shown in Figure 54, namely, Configure, Design, Monitor, and Status. After launch the GUI, its default tab is Monitor. To go to the other three tabs, simply click the tab you would like to go.

In the GUI used with this EVM, Configure is used to configure the EVM settings through PMBus commands. Design is mainly used to make tuning control loop parameters and to set up the Feed-Forward control non-linear gains. Monitor is used to monitor the board operation. Status is mainly used to show fault and/or warnings.

A.8.2 Operation Monitoring

After the designer GUI launched, the Monitor tab is presented by default as shown in Figure 54. This tab provides a quick overview of operation status with some settings changeable as well. This tab also provides oscilloscope type of plot view in real time operation. The number of scope windows can be adjusted by check or un-check upper left square boxes to show or to hide these scope plot windows.

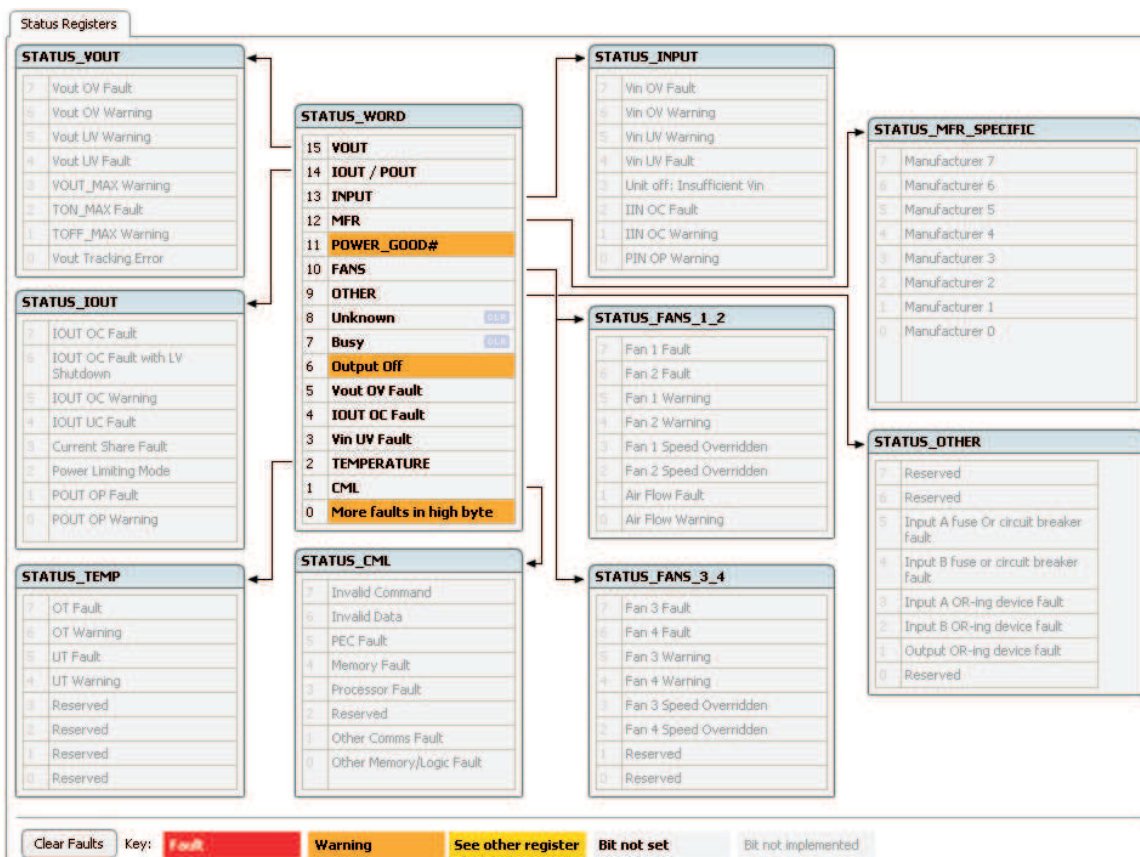


Figure 55. Designer GUI Status

A.8.3 Operation Status

After click the Status tab as shown in Figure 54, the EVM operation status is shown as in Figure 55. All grayed entries are candidates that can be implemented. Those in black are showing current operation status which helps to indicate potential operation issues with warning or fault indications. If a fault occurred, the corresponding entry is highlighted in red. Warnings are not a fault while may remind the user that those might need attention.

A.8.4 Configuring EVM

Configure tab can help to adjust the EVM feature setup conveniently without directly accessing the firmware code. Also, it helps to navigate through the various features of the converter through the GUI.

The screenshot shows two panels from a GUI. The left panel is titled 'Configuration' and contains two tables. The first table lists configuration commands with their codes, values, and hex values. The second table lists limits with their codes, values, units, and hex values. The right panel is titled 'Manufacturer Info' and lists various manufacturer-specific commands and their values, including device ID, location, and status.

| Command | Code | Value/Edit | Hex/Edit |
|----------------------------|------|-------------|----------|
| CPCC [MFR 36] | 0xF4 | Click... | 0x01... |
| DEADBAND_CONFIG [MFR 26] | 0xEA | Click... | 0x01... |
| FREQUENCY_SWITCH | 0x33 | 200.0 kHz | 0x00C8 |
| IDEAL DIODE EMUL CONFIG | 0xFE | Enabled | 0x01 |
| LIGHT_LOAD_CONFIG [MFR 02] | 0xD2 | Click... | 0x00... |
| VFF_CONFIG [MFR 42] | 0xFA | Enabled | 0x01 |
| VOUT_COMMAND | 0x21 | 12.000 V | 0x1800 |
| VOUT_MODE | 0x20 | Exp 9 | 0x17 |
| VOUT_TRANSITION_RATE | 0x27 | 1.000 mV/µs | 0x0001 |

| Command | Code | Value/Edit | Hex/Edit |
|---------------------|------|------------|----------|
| IIN_OC_FAULT_LIMIT | 0x5B | 16.00 A | 0x0010 |
| IOUT_OC_FAULT_LIMIT | 0x46 | 38.00 A | 0x0026 |
| OT_FAULT_LIMIT | 0x4F | 50 °C | 0x0032 |
| VIN_OFF | 0x36 | 35.000 V | 0x0023 |
| VIN_ON | 0x35 | 37.000 V | 0x0025 |
| VIN_OV_FAULT_LIMIT | 0x55 | 75.000 V | 0x004B |
| VIN_UV_FAULT_LIMIT | 0x59 | 33.000 V | 0x0021 |
| VOUT_OV_FAULT_LIMIT | 0x40 | 14.000 V | 0x1C00 |
| VOUT_UV_FAULT_LIMIT | 0x44 | 3.000 V | 0x0600 |

| Command | Code | Value/Edit | Hex/Edit |
|-----------------------------|------|--------------------------------|----------|
| CMDS_DCDC_NONPAGED [MFR 21] | 0xE5 | Click... | 0x10... |
| CMDS_DCDC_PAGED [MFR 20] | 0xE4 | Click... | 0x00... |
| DEVICE_ID [MFR 45] | 0xFD | UCD31001S01 | 0x55... |
| IC_DEVICE_ID | 0xAD | UCD3138RHA | 0x55... |
| IC_DEVICE_REV | 0xAE | 0 | 0x3000 |
| MFR_DATE | 0x9D | 121115 | 0x31... |
| MFR_ID | 0x99 | TI | 0x54... |
| MFR_LOCATION | 0x9C | Dallas, TX | 0x44... |
| MFR_MODEL | 0x9A | UCD3138HS... | 0x55... |
| MFR_REVISION | 0x9B | A | 0x4100 |
| MFR_SERIAL | 0x9E | 121115 | 0x31... |
| PMBUS_REVISION | 0x98 | 1.2,1.2 - Part 1.1.2 - Rev 1.1 | 0x42 |
| SETUP_ID [MFR 23] | 0xE7 | VERSIO... | 0x56... |

| Command | Code | Value/Edit | Hex/Edit |
|----------------|------|------------|----------|
| POWER_GOOD_OFF | 0x5F | 11.000 V | 0x1600 |
| POWER_GOOD_ON | 0x5E | 11.500 V | 0x1700 |
| TON_RISE | 0x61 | 20.0 ms | 0x0014 |

| Command | Code | Value/Edit | Hex/Edit |
|-----------------------------|------|------------|----------|
| READ_DEBUG_BUFFER1 [MFR 32] | 0xF0 | Click... | 0x01... |
| READ_FREQUENCY | 0x95 | 0.0 kHz | 0x0000 |
| READ_IOUT | 0x8C | 0.00 A | 0x5800 |
| READ_TEMP_EXTERNAL | 0x8E | -353 °C | 0xFD3E |
| READ_TEMP_INTERNAL | 0x8D | 22 °C | 0xDAB6 |
| READ_VIN | 0x88 | 28.750 V | 0xDB98 |
| READ_VOUT | 0x8B | 0.000 V | 0x0000 |
| STATUS_BYTE | 0x78 | 00000000 | 0x00 |
| STATUS_WORD | 0x79 | Click... | 0x0000 |

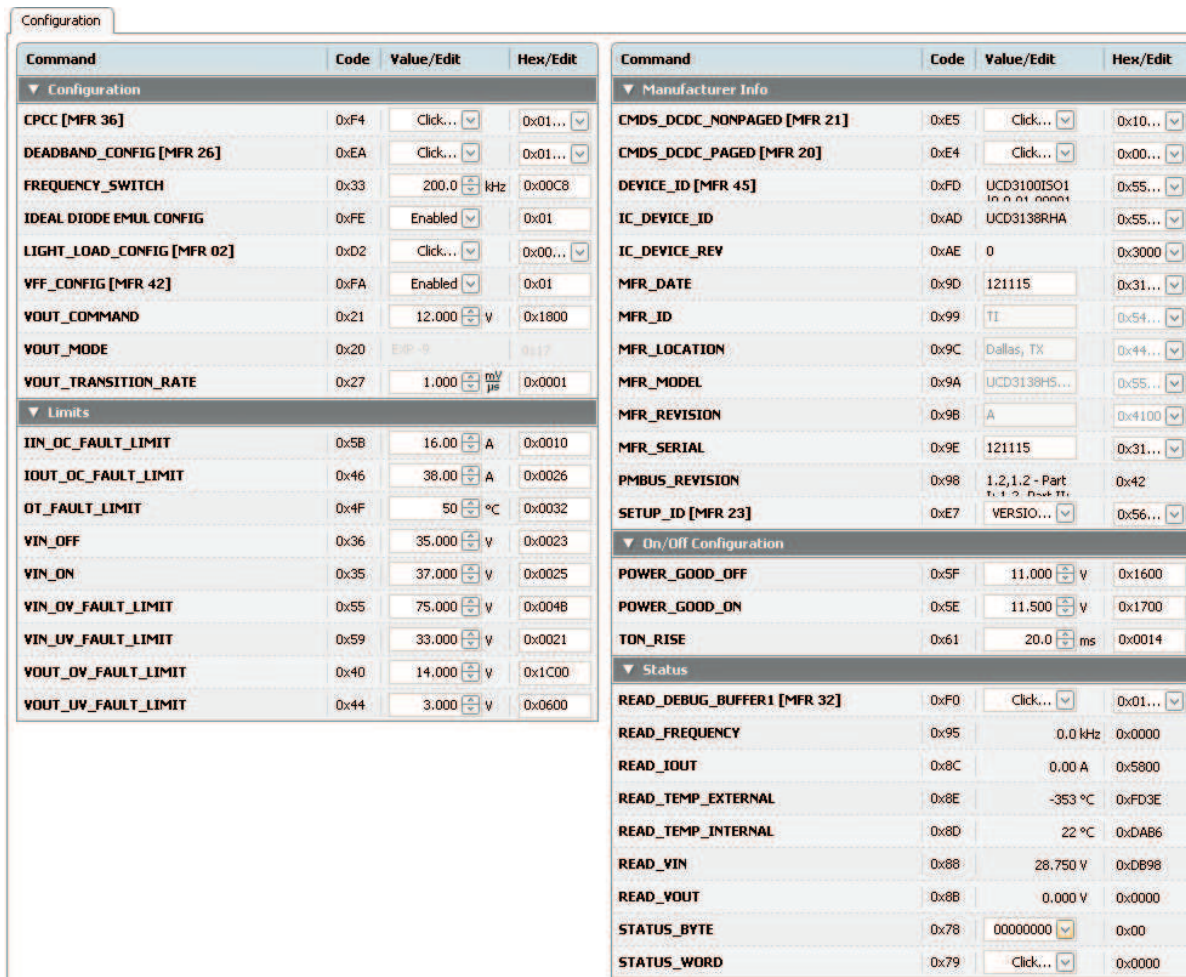
Figure 56. GUI Supported PMBus Commands

A.8.4.1 GUI Supported PMBus Commands

Figure 56 displays the various GUI based PMBus commands supported by the current version of the firmware. Adding additional standard commands is easy to do with the built in “Isolated Bit Mask” generator. This tool creates a coded index that the GUI reads from the device to determine what PMBus commands are supported. To add a standard command simply modify the bit mask and the GUI will automatically display the new command. Please contact Texas Instruments for details on the use of this tool.

A.8.4.2 Configuring EVM with GUI

In the Configure tab, change configuration is made simple. For example, to configure CPCC, the CPCC control can be accessed by clicking the drop down arrow next to the Value/Edit box on the CPCC[MFR 36] line as shown in Figure 57. As we mentioned before, maximum current 36A and maximum power 360W. Please consult Texas Instruments if there is any uncertainty to be resolved.



| Command | Code | Value/Edit | Hex/Edit |
|-----------------------------|------|---------------------------------|----------|
| Configuration | | | |
| CPCC [MFR 36] | 0xF4 | Click... | 0x01... |
| DEADBAND_CONFIG [MFR 26] | 0xEA | Click... | 0x01... |
| FREQUENCY_SWITCH | 0x33 | 200.0 kHz | 0x00C8 |
| IDEAL DIODE EMUL CONFIG | 0xFE | Enabled | 0x01 |
| LIGHT_LOAD_CONFIG [MFR 02] | 0xD2 | Click... | 0x00... |
| VFF_CONFIG [MFR 42] | 0xFA | Enabled | 0x01 |
| VOUT_COMMAND | 0x21 | 12.000 V | 0x1800 |
| VOUT_MODE | 0x20 | 0 | 0x1F |
| VOUT_TRANSITION_RATE | 0x27 | 1.000 $\frac{mV}{\mu s}$ | 0x0001 |
| Limits | | | |
| IIN_OC_FAULT_LIMIT | 0x5B | 16.00 A | 0x0010 |
| IOUT_OC_FAULT_LIMIT | 0x46 | 38.00 A | 0x0026 |
| OT_FAULT_LIMIT | 0x4F | 50 °C | 0x0032 |
| VIN_OFF | 0x36 | 35.000 V | 0x0023 |
| VIN_ON | 0x35 | 37.000 V | 0x0025 |
| VIN_OV_FAULT_LIMIT | 0x55 | 75.000 V | 0x004B |
| VIN_UV_FAULT_LIMIT | 0x59 | 33.000 V | 0x0021 |
| VOUT_OV_FAULT_LIMIT | 0x40 | 14.000 V | 0x1C00 |
| VOUT_UV_FAULT_LIMIT | 0x44 | 3.000 V | 0x0600 |
| Manufacturer Info | | | |
| CMDS_DCDC_NONPAGED [MFR 21] | 0xE5 | Click... | 0x10... |
| CMDS_DCDC_PAGED [MFR 20] | 0xE4 | Click... | 0x00... |
| DEVICE_ID [MFR 45] | 0xFD | UCD31001S01 | 0x55... |
| IC_DEVICE_ID | 0xAD | UCD3138RHA | 0x55... |
| IC_DEVICE_REV | 0xAE | 0 | 0x3000 |
| MFR_DATE | 0x9D | 121115 | 0x31... |
| MFR_ID | 0x99 | TI | 0x54... |
| MFR_LOCATION | 0x9C | Dallas, TX | 0x44... |
| MFR_MODEL | 0x9A | UCD3138H5... | 0x55... |
| MFR_REVISION | 0x9B | A | 0x4100 |
| MFR_SERIAL | 0x9E | 121115 | 0x31... |
| PMBUS_REVISION | 0x98 | 1.2,1.2 - Part 1.1.1 - Rev. 1.1 | 0x42 |
| SETUP_ID [MFR 23] | 0xE7 | VERSIO... | 0x56... |
| On/Off Configuration | | | |
| POWER_GOOD_OFF | 0x5F | 11.000 V | 0x1600 |
| POWER_GOOD_ON | 0x5E | 11.500 V | 0x1700 |
| TON_RISE | 0x61 | 20.0 ms | 0x0014 |
| Status | | | |
| READ_DEBUG_BUFFER1 [MFR 32] | 0xF0 | Click... | 0x01... |
| READ_FREQUENCY | 0x95 | 0.0 kHz | 0x0000 |
| READ_IOUT | 0x8C | 0.00 A | 0x5800 |
| READ_TEMP_EXTERNAL | 0x8E | -353 °C | 0xFD3E |
| READ_TEMP_INTERNAL | 0x8D | 22 °C | 0xDAB6 |
| READ_VIN | 0x88 | 28.750 V | 0xDB98 |
| READ_VOUT | 0x8B | 0.000 V | 0x0000 |
| STATUS_BYTE | 0x78 | 00000000 | 0x00 |
| STATUS_WORD | 0x79 | Click... | 0x0000 |

Figure 57. Configure CPCC

As one more example, in the following, we will describe how to configure the dead time. Configure other functions are made in the similar way. Again, please consult Texas Instruments if there is any uncertainty to be resolved before making your configuration.

A.8.4.3 Configuring Dead Time

Click the drop down arrow next to the Value/Edit box on the DEADBAND_CONFIG [MFR 26] line, a dialogue box of Figure 58 is present to allow configuring the dead time.

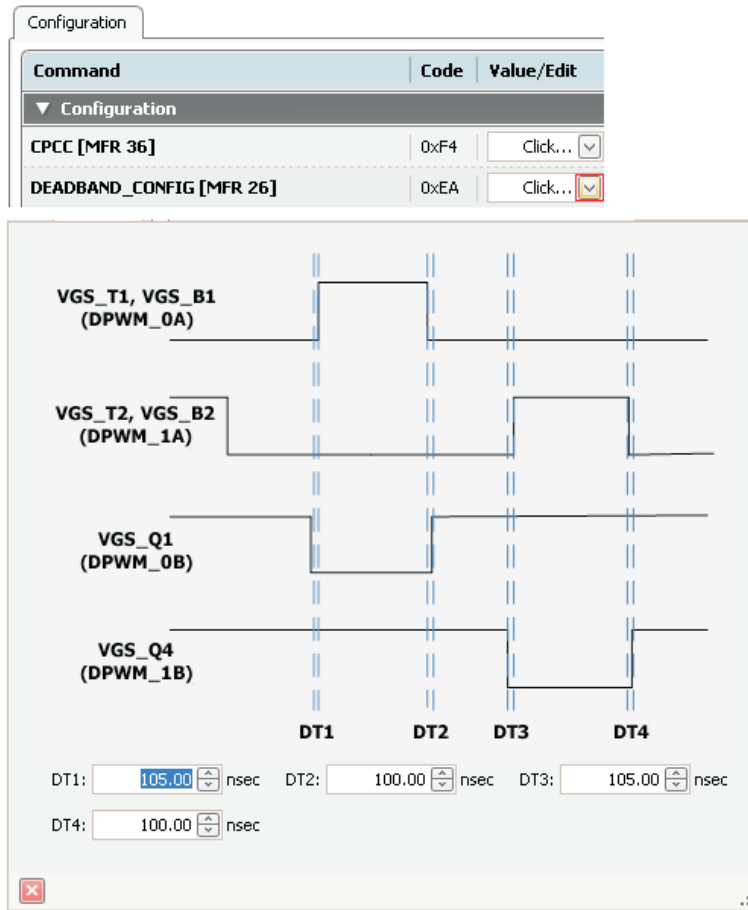


Figure 58. Configuring Dead Time

A.8.5 Tuning Control Loop Using GUI Design

A.8.5.1 Options to Program Digital Control Loop

The GUI comes equipped with 3 different ways to program the UCD3138 digital control loop compensator. Table 9 lists the three options, (a) using K_0 , f_z , Q_z , and f_p ; (b) using K_0 , f_{z1} , f_{z2} , and f_p ; (c) using K_p , K_i , K_d , and α .

In option (c), the compensator is described by Device PID. In this context, K_p , K_i , K_d and α are the raw register values used to configure the positions of the poles and zeros of the compensator. SC is a gain scaling term. Although it is normally set to zero it provides additional gain for situations where the power stage gain may be low. PRD is used to configure the minimum operating period and KCOMP is used to configure the maximum operating period. In the context of the compensator they are simply gain terms that modify the overall transfer function by a fixed value. It is important to be aware that the proper way to configure PRD and KCOMP varies based on the control topology implemented.

Table 9. Programming Digital Control Loop

| SYSTEM NAME | TRANSFER FUNCTIONS |
|---|---|
| Complex Zeros (K_0 , f_z , Q_z , f_p) | $\frac{s^2}{(2 \times \pi \times f_z)^2} + \frac{s}{2 \times \pi \times f_z \times Q_z} + 1$ $\frac{s}{2 \times \pi \times K_0} \times \left(\frac{s}{2 \times \pi \times f_p} + 1 \right)$ |
| Real Zeros (K_0 , f_{z1} , f_{z2} , f_p) | $\frac{s^2}{(2 \times \pi \times f_z)^2} + \frac{s}{2 \times \pi \times f_z \times Q_z} + 1$ $\frac{s}{2 \times \pi \times K_0} \times \left(\frac{s}{2 \times \pi \times f_p} + 1 \right)$ |
| Device PID (K_p , K_i , K_d , α) | $1000 \times \left(K_p + K_i \times \frac{1+z^{-1}}{1-z^{-1}} + K_d \times \frac{1-z^{-1}}{1-\alpha \times 2^{-8} \times z^{-1}} \right) \times 2^{-SC} \times KCOMP \times 2^{-19} \times \frac{1}{2^4 \times (PRD + 1)}$ |

The compensator of this EVM is configured to acquire one sample per switching cycle, T_s , as defined by Equation (17) where $T_{DPWM} = 250$ ps,

$$T_s = 16 \times (PRD + 1) \times T_{DPWM} \quad (17)$$

When the converter operates in PWM mode $KCOMP = PRD$ and the “Device PID” option in Table 9 is expressed in Equation (16) which correctly describes the behavior of the compensator. For clarity Equation (18) displays the exact transfer function used in PWM mode operation.

$$1000 \times \left(K_p + K_i \times \frac{1+z^{-1}}{1-z^{-1}} + K_d \times \frac{1-z^{-1}}{1-\alpha \times 2^{-8} \times z^{-1}} \right) \times \frac{2^{-SC} \times PRD \times 2^{-19}}{2^4 \times (PRD + 1)} \quad (18)$$

Equation (18) is based on a fixed sample rate. This means Equation (18) is assumed with one switching frequency. The value of that frequency is inside the variable z ;

$$z = e^{sT_s} \quad (19)$$

where T_s is the switching period, i.e., the reciprocal of the switching frequency. Let’s make it clear: in PWM mode, the switching frequency is fixed say at 200kHz such that T_s is a fixed and the only value. Figure 59 shows an example of Bode plot output from the GUI. Figure 60 shows the PID coefficients used. Figure 61 shows the schematics used to obtain the Bode Plots in Figure 59 with the PID coefficients shown in Figure 60.

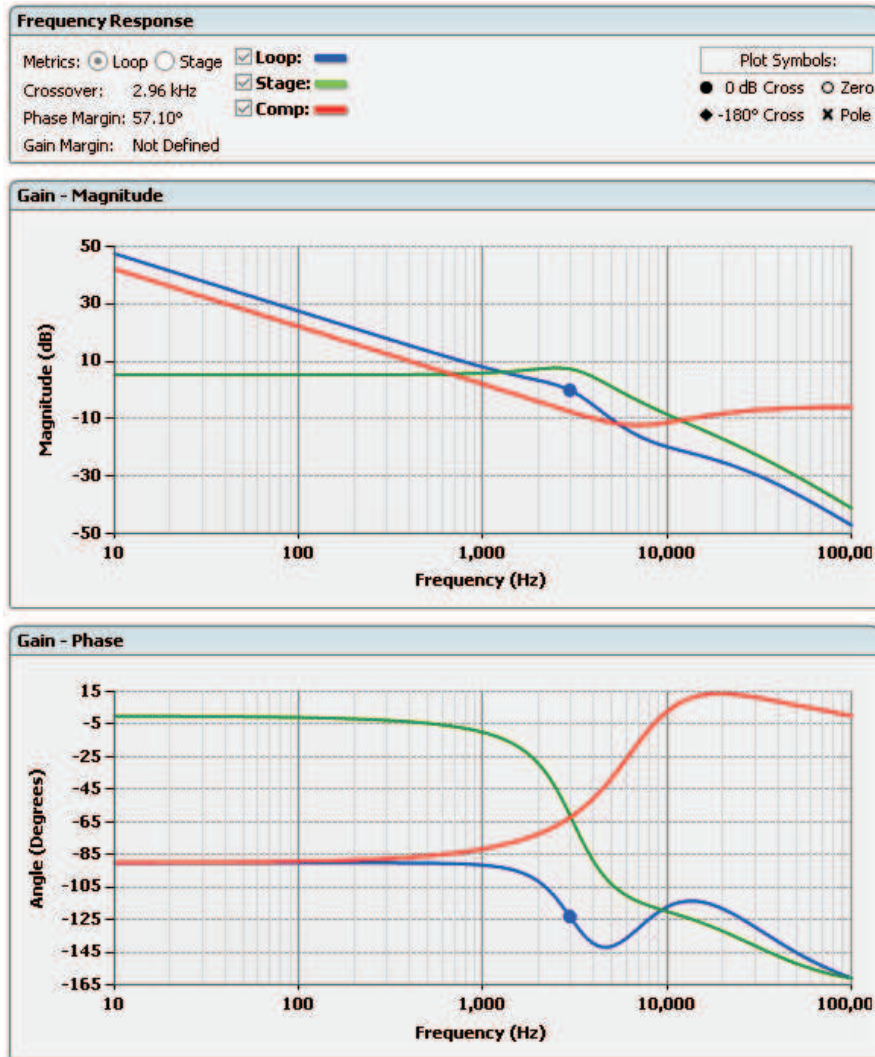


Figure 59. Bode Plots from GUI

```

CLA Gains Review - DC-DC HSF B @ Address 88d
C Code:
//This is the C code for the loop currently selected.
//It also reflects the values currently set in the GUI and
//may not reflect what was last written to the device.
//Write coefficients for the code to reflect the device.
//Time: 12/6/2012 6:08 PM

Filter0Regs.FILTERCTRL.bit.NL_MODE = 1; //Symmetric

// Coefficient set A (0)
Filter0Regs.FILTERKPCOEF0.bit.KP_COEF_0 = 1500;
Filter0Regs.FILTERKICOEF0.bit.KI_COEF_0 = 160;
Filter0Regs.FILTERKDCOEF0.bit.KD_COEF_0 = 2000;

// Coefficient set B (1)
Filter0Regs.FILTERKPCOEF0.bit.KP_COEF_1 = 5000;
Filter0Regs.FILTERKICOEF0.bit.KI_COEF_1 = 250;
Filter0Regs.FILTERKDCOEF0.bit.KD_COEF_1 = 10000;

// Coefficient set C (2)
Filter0Regs.FILTERKPCOEF1.bit.KP_COEF_2 = 10000;
Filter0Regs.FILTERKICOEF1.bit.KI_COEF_2 = 500;
Filter0Regs.FILTERKDCOEF1.bit.KD_COEF_2 = 5500;

// Coefficient set D (3)
Filter0Regs.FILTERKICOEF1.bit.KI_COEF_3 = 500;

// Alpha coefficient banks
Filter0Regs.FILTERKDALPHA.bit.KD_ALPHA_0 = 150;
Filter0Regs.FILTERKDALPHA.bit.KD_ALPHA_1 = 25;
    
```

Figure 60. PID Coefficients Used in Voltage Loop

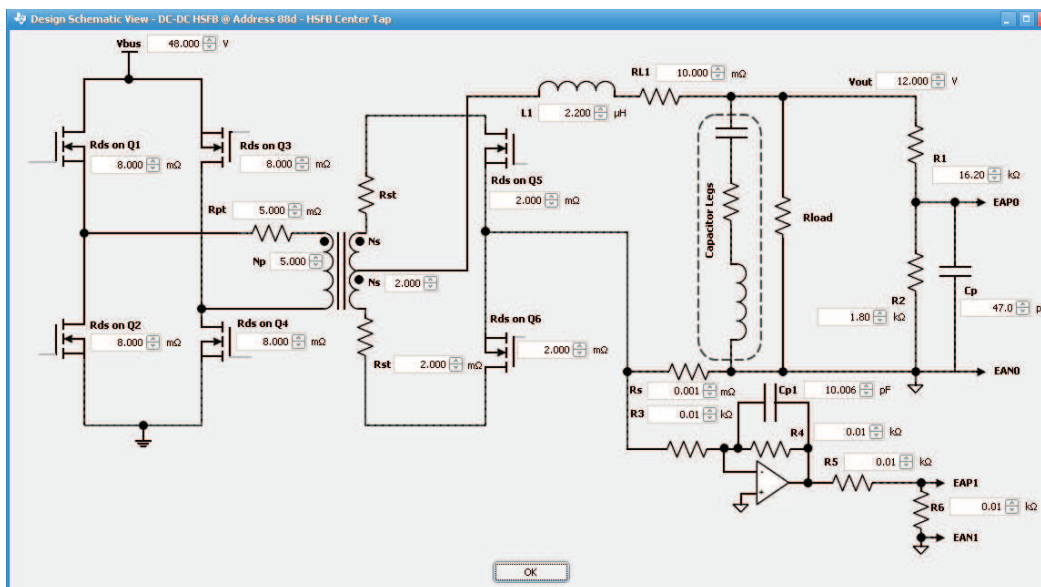


Figure 61. The Schematics Used in the Bode Plots Calculation

A.9 Firmware Development for HSF B Power Converter

Please contact TI for additional information regarding UCD3138 digital HSF B firmware development.

A.10 References

1. UCD3138 Datasheet, *Highly Integrated Digital Controller for Isolated Power*, (Texas Instruments, Literature Number SLUSAP2), 2012
2. UCD3138CC64EVM-030 Evaluation Module and User's Guide, *Programmable Digital Power Controller Control Card Evaluation Module*, (Texas Instruments Literature Number SLUU886), 2012
3. TI Application Manual, *UCD3138 Digital Power Peripherals Programmer's Manual*, (Texas Instruments Literature Number SLUU995)
4. TI Application Manual, *UCD3138 Monitoring and Communications Programmer's Manual*, (Texas Instruments Literature Number SLUU996)
5. TI Application Manual, *UCD3138 ARM and Digital System Programmer's Manual*, (Texas Instruments Literature Number SLUU994)
6. User Guide, *UCD3138 Isolated Power Fusion GUI*, (please contact TI). Note this User Guide is also available in the GUI after installation.

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- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

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